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Intel® Server Board SE7505VB2

Technical Product Specification

Intel part number C32194-002

Revision 1.2

April 2004

Enterprise Platforms and Services Marketing

Revision History

Date	Revision Number	Modifications
January 2003	1.0	Initial Release
March 2003	1.1	Added memory cooling duct information, added section on BIOS event log, incorporated Technology Leadership terminology, and corrected miscellaneous minor technical details.
April 2004	1.2	New graphics for Mechanical Changes.

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1. Introduction

The Intel® Server Board SE7505VB2 Technical Product Specification (TPS) provides technical details for the server board's functional architecture and feature set. It also provides a high-level detail of some of the board's functional sub-systems.

This document is intended to be the technical reference for this board. Updates to this document will be made via the Specification Update published monthly from the date of product launch. Please refer to the Intel Server Board SE7505VB2 support website for any updates to this document: http://support.intel.com/support/motherboards/server/se7505vb2.

2. SE7505VB2 Server Board Overview

The Intel[®] Server Board SE7505VB2 is a monolithic printed circuit board with features that were designed to support the general purpose, pedestal server market and meet the needs of a high end workstation system as well. The architecture is based around the Intel[®] E7505 chipset and is capable of supporting one or two Intel[®] Xeon[™] processors with 512KB L2 cache and up to 8GB of memory.

2.1 Intel[®] Server Board SE7505VB2 Feature Set

The Intel Server Board SE7505VB2 supports the following feature set:

- Processor/FSB support
 - Dual Intel Xeon processors with 512KB L2 cache using the 604-pin FCPGA processor package
 - 533 MHz FSB or 400 MHz FSB support
 - 4.2 GB/sec Bus Bandwidth
 - One version 9.1 compliant VRD to supply CPU core voltage
- Intel E7505 chipset components
 - MCH memory controller
 - P64H2 64-bit I/O Hub
 - ICH4 I/O controller
 - FWH Firmware Hub
- Glue4-PAL
- Support for up to four DDR266 compliant ECC DDR DIMMs providing up to 8 GB of memory
- Three separate and independent PCI buses:
 - Segment A: Two PCI 32-bit/33-MHz, 5 V connectors supporting full length PCI add-in cards and three embedded devices:
 - 2D/3D graphics controller: ATI Rage XL video controller with 8 MB of SDRAM
 - One Intel 10/100 82550PM Fast Ethernet Controller
 - Dual port Serial ATA controller: Silicon Image 3112A
 - Segment B: Two PCI-X 64-bit/100-MHz, 3.3 V slots supporting full length PCI / PCI-X add-in cards
 - Segment C: One PCI 64-bit/66-MHz, 3.3 V slot supporting full length PCI add-in cards and one embedded component:
 - Intel 82540EM 10/100/1000 gigabit Ethernet controller
- LPC (Low Pin Count) bus segment with two embedded devices:
 - Super I/O (sIO) controller chip, Winbond* 83627HF, providing all PC-compatible I/O (floppy, serial, keyboard, mouse, parallel) and integrated hardware monitoring
 - Flash ROM device for system BIOS: Intel 8 megabit N82802AC Flash ROM

- Graphic AGP 3.0 Pro50 watt support
 - Support 2X, 4X and 8X AGP protocol
 - AGP Pro50 supported by additional power pins in 4X and 8X mode
 - Support 1.5V signal levels only
 - Maximum of 2.03 GB/sec Bus Bandwidth
- Three external Universal Serial Bus (USB) ports with an additional internal header providing one optional USB ports for front panel support.
- Two IDE connectors, supporting up to four ATA-100 compatible devices
- Support for up to four system fans and two processor fans
- SSI-compliant connectors for SSI interface support: front panel and power connectors.

The following figure below shows the functional blocks of the server board and the plug-in modules that it supports.

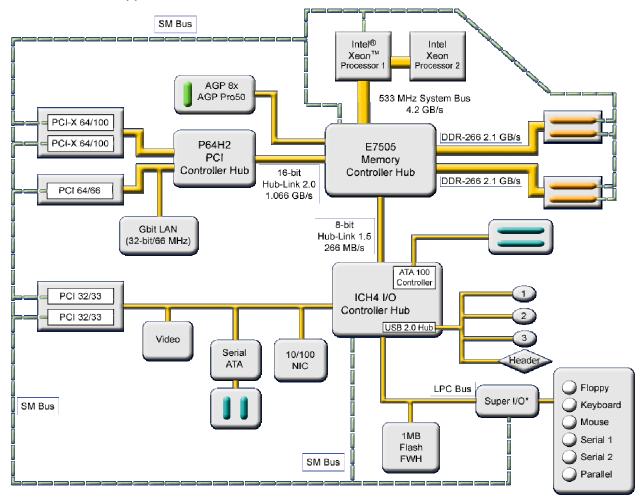


Figure 1. The Board Block Diagram

3. Functional Architecture

This chapter provides a high-level description of the functionality distributed between the architectural blocks of the Intel[®] Server Board SE7505VB2.

3.1 Processor and Memory Subsystem

The Intel® chipset E7505 provides a 36-bit address, 64-bit data processor host bus interface, operating at 533 MHz in the AGTL+ signaling environment. The MCH component of the chipset provides an integrated memory controller, an 8-bit hub interface, and one 16-bit hub interfaces.

The hub interface provides the interface to two 64-bit/100-MHz PCI-X buses and one 64-bit/66-MHz PCI bus via the P64H2, and the interface to two 32-bit/33-MHz PCI buses via the ICH4. The board directly supports up to 8 GB of ECC memory, using four DDR266 compliant ECC DIMMs. The ECC implementation in the MCH can detect and correct single-bit errors (SBE), detect multiple-bit errors (MBE), and supports Intel® x4 Single Data Device Correction (Intel x4 SDDC) feature with x4 DIMMs.

3.1.1 Processor Support

The Intel Server Board SE7505VB2 supports one or two processors in the 604-pin FCPGA package. When two processors are installed, all processors must be of identical revision, core voltage, and bus/core speed. When only one processor is installed, it should be in the socket labeled CPU1 and the other socket must be empty. The support circuitry on the server board consists of the following:

- Dual 604-pin processor sockets supporting 533MHz FSB Intel Xeon processors.
- Processor host bus AGTL+ support circuitry.

Processor Family	Package Type	Frequency	Cache Size	Front Side Bus Speed
Intel Xeon	FCPGA	3.06GHz	512KB	533
Intel Xeon	FCPGA	2.8 GHz	512KB	400 / 533
Intel Xeon	FCPGA	2.67 GHz	512KB	400 / 533
Intel Xeon	mPGA / FCPGA	2.4 GHz	512KB	400 / 533
Intel Xeon	mPGA / FCPGA	2.2 GHz	512KB	400 / 533
Intel Xeon	mPGA / FCPGA	2.0GHz	512KB	400 / 533
Intel Xeon	mPGA / FCPGA	1.8GHz	512KB	400

Table 1. Processor Support Matrix

Notes:

- Processors must be populated in sequential order. Processor socket 1 must be populated before processor socket 2.
- The board is designed to provide up to 65A of current per processor. Processors with higher current requirements are not supported.
- No terminator is required in the second processor socket when using a uni-processor configuration.

In addition to the circuitry described above, the processor subsystem contains the following:

- Reset configuration logic
- Processor module presence detection logic
- Server management registers and sensors

3.1.1.1 Processor VRD

The Intel Server Board SE7505VB2 has a single VRD (Voltage Regulator Down) to support two processors. It is compliant with the VRM 9.1 specification and provides a maximum of 130 AMPs, which is capable of supporting the requirements for two Intel[®] Xeon™ processors.

The board hardware and PMC (Power Management Controller) must read the processor VID (voltage identification) bits for each processor before turning on the VRD. If the VIDs of the two processors are not identical, then the PMC will not turn on the VRD.

3.1.1.2 Reset Configuration Logic

The BIOS determines the processor stepping, cache size, etc through the CPUID instruction. The requirements are as follows:

- All processors in the system must operate at the same frequency, have the same cache sizes, and same VID. No mixing of product families is supported.
- Processors run at a fixed speed and cannot be programmed to operate at a lower or higher speed.

The processor information is read at every system power-on.

Note: The processor speed is the processor power on reset default value. No manual processor speed setting options exist either in the form of a BIOS setup option or jumpers.

3.1.1.3 Processor Module Presence Detection

Logic is provided on the baseboard to detect the presence and identity of installed processors. The PMC checks the logic and will not turn on the system DC power unless the VIDs of both the processors match in a DP configuration.

3.1.1.4 Interrupts and APIC

Interrupt generation and notification to the processors is done by the APICs in the ICH4 and the P64H2 using messages on the front side bus.

3.1.2 Memory Subsystem

The baseboard supports up to four DIMM slots for a maximum memory capacity of 8 GB. The DIMM organization is x72, which includes eight ECC check bits. The memory interface runs at 266MT/s. The memory controller supports memory scrubbing, single-bit error correction and multiple-bit error detection and Intel x4 SDDC support with x4 DIMMs. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs.

The figure below provides a block diagram of the memory sub-system implemented on the board.

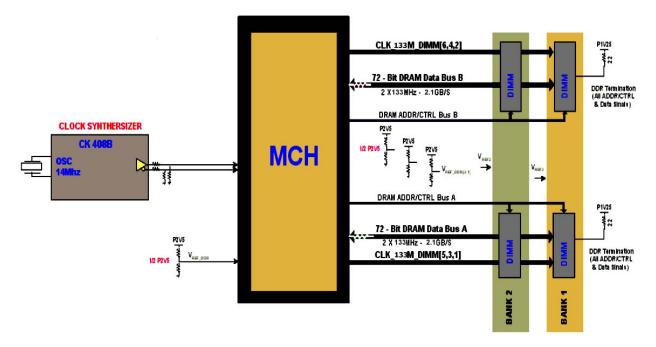


Figure 2. Memory Sub-system Block Diagram

3.1.2.1 Memory DIMM Support

The board supports DDR266-compliant ECC DIMMS operating at 266MT/s. Only DIMMs tested and qualified by Intel or a designated memory test vendor are supported on this board. A list of qualified DIMMs is available at http://support.intel.com/support/motherboards/server/se7505vb2. Note that all DIMMs are supported by design, but only fully qualified DIMMs will be supported on the board.

The minimum supported DIMM size is 128 MB. Therefore, the minimum main memory configuration is 1 x 128 MB or 128 MB. The largest size DIMM supported is a 2 GB registered DDR266 ECC DIMM based on 512 megabit technology. Therefore the maximum main memory configuration is 4 x 2 GB or 8 GB.

- Only registered DDR266 compliant, ECC, DDR memory DIMMs will be supported
- ECC single-bit errors (SBE) will be corrected and multiple-bit error (MBE) will be detected.
- Intel server board also supports Intel x4 SDDC with x4 DIMMs.
- The maximum memory capacity is 8 GB
- The minimum memory capacity is 128 MB

3.1.2.2 Memory Configuration

The memory interface between the MCH and the DIMMs is 144-bits wide (72-bits for each bank).

There are two banks of DIMMs, labeled 1 and 2. Bank 1 contains DIMM socket locations 1A and 1B. Bank 2 contains 2A and 2B. The sockets associated with each bank are located next to each other and the DIMM socket identifiers are marked on the baseboard silkscreen, near the DIMM socket.

For designs that require a lower price point, a single 128 MB DIMM can be populated in the DIMM1A socket. When a single DIMM is installed, interleaving and Intel x4 SDDC are not available. Bank 2 will only operate with two DIMMs installed.

The baseboard's signal integrity and cooling are optimized when memory banks are populated in order. Before populating either DIMM socket in bank 2, both DIMMs in bank 1 must be populated. No empty DIMM sockets are allowed between populated DIMMs.

DIMM and memory configurations must adhere to the following:

- DDR266 ECC, registered, DDR DIMM modules
- DIMM organization: x72 ECC
- Pin count: 184
- DIMM capacity: 128 MB, 256 MB, 512 MB, 1 GB, 2GB DIMMs
- Serial PD: JEDEC Rev 2.0
- Voltage options: 3.3 V (VDD/VDDQ)
- Interface: SSTL2

3.1.2.3 Memory Cooling

The SE7505VB2 server board supports DDR memory in a variety of sizes and densities (see Table 4). Due to the specific orientation of the memory on the SE7505VB2 server board, certain memory densities and configurations are more difficult to cool in chassis that provide traditional front to back airflow such as the Intel SC5200 and SC5250-E server chassis. To ensure the memory used with this board has sufficient thermal margin to operate within specifications, Intel has designed a memory cooling duct specifically for the SE7505VB2 server board. Intel's testing has shown only 2GB and stacked 1GB (low profile) DIMMs are thermally at risk. If your specific design uses either of these size memory parts, contact Intel Customer Support and request the SE7505VB2 server board memory cooling duct, part number C28482-001.

Table 2. Memory Bank Labels

Memory DIMM	Bank
J9H1 (DIMM 1A), J9H2 (DIMM 1B)	1
J9J1 (DIMM 2A), J9J2 (DIMM 2B)	2

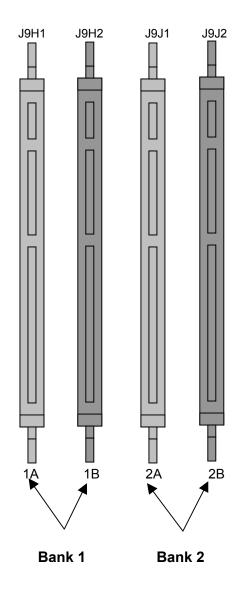


Figure 3. Memory Bank Label Definition

3.1.2.4 I²C Bus

The I²C bus is used by the system BIOS to retrieve DIMM information needed to program the MCH memory registers, which are required to boot the system.

The following table provides the I²C addresses for each DIMM slot.

Table 3. I²C Addresses for Memory Module SMB

Device	Address
DIMM 1A	0xA0
DIMM 1B	0xA2
DIMM 2A	0xA4
DIMM 2B	0xA6

3.1.2.5 DRAM ECC

The ECC used for DRAM provides Intel x4 SDDC technology for x4 SDRAMs. DRAMs that are x8 use the same algorithm but will not have Intel x4 SDDC technology, since at most only four bits can be corrected with this ECC.

The method provides more ECC bits so each ECC word can correct more than a single-bit failure. This is possible because different mathematical algorithms provide multiple-bit correction with the right number of data bits and ECC bits. For example, a 144-bit ECC word that consists of 128 data bits and 16 ECC bits can be used to correct up to 4 bit errors within certain bit fields of data. These four bits must be adjacent, not random. Even though the ratio of the ECC bits to data bits is the same as the previous example (16/128 vs. 8/64), the longer ECC word allows for a correction and detection algorithm that is more efficient.

3.2 The Intel® E7505 Chipset

The Intel Server Board SE7505VB2 is designed around the Intel E7505 chipset. The chipset provides an integrated I/O bridge and memory controller, and a flexible I/O subsystem core (PCI / PCI-X). This is targeted for multiprocessor systems and standard high-volume servers. The chipset consists of three components:

- MCH: Memory Control Hub. The MCH accepts access requests from the host (processor) bus and directs those accesses to memory or to one of the PCI buses. The MCH monitors the host bus, examining addresses for each request. Accesses may be directed to a memory request queue for subsequent forwarding to the memory subsystem, or to an outbound request queue for subsequent forwarding to one of the PCI buses. The MCH also accepts inbound requests from the P64H2 and the ICH4. The MCH is responsible for generating the appropriate controls to control data transfer to and from memory.
- P64H2: PCI-X 64bit Hub 2.0 I/O Bridge. The P64H2 provides the interface for two PCI-X buses capable of 133MHz operation. The P64H2 is both master and target on both buses.

■ ICH4: I/O Controller Hub 4. The ICH4 controller has several components. It provides the interface for a 32-bit/33-MHz PCI bus. The ICH4 can be both a master and a target on that PCI bus. The ICH4 also includes a USB 2.0 controller and an IDE controller. The ICH4 is also responsible for much of the power management functions, with ACPI control registers built in. The ICH4 also provides a number of GPIO pins and has the LPC bus to support low speed legacy I/O.

The MCH, P64H2, and ICH4 chips provide the pathway between processor and I/O systems. The MCH is responsible for accepting access requests from the host (processor) bus, and directing all I/O accesses to one of the PCI buses or legacy I/O locations. If the cycle is directed to one of the 64-bit PCI segments, the MCH communicates with the P64H2 through a private interface called the HI (Hub Interface). If the cycle is directed to the ICH4, the cycle is output on the MCH's 8-bit HI 1.5 bus. The P64H2 translates the HI 2.0 bus operation to a 64-bit PCI signaling environment operating between 133 MHz and 33 MHz.

The HI 2.0 bus is 16 bits wide and operates at 66 MHz with 512MT/s, providing over 1 GB per second of bandwidth.

All I/O for the board, including PCI and PC-compatible I/O, is directed through the MCH and then through either the P64H2 or the ICH4 provided PCI buses.

- The ICH4 provides one 32-bit/33-MHz PCI bus hereafter called P32-A.
- The P64H2 provides one 64-bit/100-MHz PCI-X bus, hereafter called P64-B, and one 64bit/66MHz PCI bus, hereafter called P64-C.

This independent bus structure allows all three PCI buses to operate independently and concurrently providing additional bandwidth to the system.

3.2.1 MCH Memory Architecture Overview

The MCH supports a 144-bit wide memory sub-system that can support a maximum of 8 GB of DDR266 memory using 2 GB DIMMs. This configuration needs external registers for buffering the memory address and control signals. The four chip selects are registered inside the MCH and need no external registers for chip selects.

The memory interface runs at 266MT/s. The memory interface supports a 72-bit or 144-bit wide memory array. It uses fifteen address lines (BA [1:0] and MA [12:0]) and supports 64 Mb, 128 Mb, 256 Mb, 512 Mb DRAM densities. The DDR DIMM interface supports memory scrubbing, single-bit error correction, and multiple bit error detection and Intel x4 SDDC with x4 DIMMs.

3.2.1.1 DDR Configurations

The DDR interface supports up to 8 GB of main memory and supports single- and double-density DIMMs. The DDR can be any industry-standard DDR. The following table shows the DDR DIMM technology supported.

Address Bits DIMM SDRAM # SDRAM Devices / DIMM Rows / Banks / SDRAM Density Rows / Banks Organization Organization Capacity Column 9/1/4 12/2/10 128MB 16M x 72 128Mbit 16M x 8 256MB 12/2/10 32M x 72 64Mbit 16M x 4 36/2/4 256MB 32M x 72 128Mbit 32M x 4 18/1/4 12/2/11 256MB 18/2/4 32M x 72 128Mbit 16M x 8 12/2/10 256MB 32M x 72 32M x 8 9/1/4 13/2/10 256Mbit 512MB 64M x 72 256Mbit 64M x 4 18/1/4 13/2/11 512MB 64M x 72 32M x 8 18/2/4 13/2/10 256Mbit 512MB 64M x 72 9/1/4 13/2/11 512Mbit 64M x 8 128M x 72 36/2/4 13/2/11 1GB 256Mbit 64M x 4 1GB 64M x 8 18/2/4 128M x 72 512Mbit 13/2/11 1GB 128M x 72 512Mbit 128M x 4 18/1/4 13/2/12 2GB 256M x 72 512Mbit 128M x 4 36/2/4 13/2/12

Table 4. Supported DDRs

3.2.2 Memory Controller Hub (MCH)

The MCH is a 1005-ball FC-BGA device and uses the proven components of previous generations like the Intel Xeon processor bus interface unit, the hub interface unit, and the DDR memory interface unit. In addition, the MCH incorporates a hub interface (HI). The HI interface allows the MCH to directly interface with the P64H2. The MCH also increases the main memory interface bandwidth and maximum memory configuration with a 144-bit wide memory interface.

The MCH integrates the following main functions:

- An integrated high performance main memory subsystem.
- An HI 2.0 bus which provides an interface to the P64H2
- An HI 1.5 bus which provides an interface to the ICH4
- AGP pro slot: Video controller with 3D/2D graphics accelerator

Other features provided by the MCH include the following:

- Full support of ECC on the processor bus
- Full support of Intel x4 SDDC on the memory interface with x4 DIMMs
- Twelve deep in-order queue, two deep defer queue
- Full support of registered DDR266 ECC DIMMs.
- Support for 2 GB DDR memory modules
- Memory scrubbing

3.2.2.1 AGP 8X Bus

The AGP 8X bus features include the following:

- Single AGP device
- AGP interface asynchronously coupled to core
- AGP 3.0 specification compliant
- AGP 8X / 4X / 2X at 1.5V
- 0.8V and 1.5V AGP electrical. No 3.3V support
- Isochronous support for AGP 8X, non-snooped
- 32 deep AGP request queue
- 32-bit upstream address support for inbound AGP and PCI cycles
- 32-bit downstream address support for outbound PCI and fast write cycles

3.2.3 P64H2

The P64H2 is a 567-ball FC-BGA device that provides an integrated I/O bridge for a high-performance data flow path between the HI 2.0 bus and the 64-bit I/O subsystem. This subsystem supports peer 64-bit PCI-X segments. Because it has two PCI interfaces, the P64H2 can provide large and efficient I/O configurations. The P64H2 functions as the bridge between the HI 2.0 interface and the two 64-bit PCI-X I/O segments. The HI interface can support 1GB/s of data bandwidth.

3.2.3.1 PCI Bus P64-B I/O Subsystem

P64-B supports two 184-pin, 3.3-volt keyed, 64-bit PCI expansion slot connectors running at 100MHz. Both of the slots support 184-pin, 3.3V keyed, 64-bit PCI-X expansion cards. Both slots support full-length PCI-X or PCI add-in cards.

The BIOS is responsible for setting the bus speed of P64-B. The bus speed runs at the speed of the slowest card installed.

3.2.3.2 PCI Bus P64-C I/O Subsystem

P64-C supports the following embedded devices and connectors:

- One 184-pin, 3.3-volt keyed, 64-bit PCI expansion slot connector running at 66MHz. This slot is capable of supporting a full-length add-in PCI card
- One integrated Intel[®] 82540EM fast Ethernet gigabit (10/100/1000) controller

The BIOS is responsible for setting the bus speed of P64-C. The bus speed runs at the speed of the slowest card installed.

3.2.4 ICH4

The ICH4 is a multi-function device, housed in a 421-pin BGA device, providing a HI 1.5 to PCI bridge, a PCI IDE interface, a PCI USB controller, and a power management controller. Each function within the ICH4 has its own set of configuration registers. Once configured, each appears to the system as a distinct hardware controller sharing the same PCI bus interface.

The primary role of the ICH4 is to provide the gateway to all PC-compatible I/O devices and features. The board uses the following the ICH4 features:

- PCI bus interface
- LPC bus interface
- IDE interface, with Ultra DMA 100 capability
- Universal Serial Bus (USB) 2.0 interface
- PC-compatible timer/counter and DMA controllers
- APIC and 8259 interrupt controller
- Power management
- System RTC
- General purpose I/O (GPIO)

The following are the descriptions of how each supported feature is used on the board.

3.2.4.1 PCI Bus P32-A I/O Subsystem

The ICH4 provides a legacy 32-bit PCI subsystem and acts as the central resource on this PCI interface. P32-A supports the following embedded devices and connectors:

- An ATI Rage XL video controller with 3D/2D graphics accelerator
- Silicon Image 3112A dual channel SATA controller
- One Intel[®] 82550PM network controller
- Two expansion slots capable of supporting full length PCI add-in cards operating at 33 MHz

3.2.4.2 PCI Bus Master IDE Interface

The ICH4 acts as a PCI-based Ultra DMA 100 IDE controller that supports programmed I/O transfers and bus master IDE transfers. The ICH4 supports two IDE channels, supporting two drives each (drives 0 and 1). The baseboard provides two 40-pin (2x20) IDE connectors to access the IDE functionality.

The IDE interface supports Ultra DMA 100 Synchronous DMA Mode transfers on each 40-pin connector.

3.2.4.3 USB Interface

The ICH4 contains three USB 2.0 controllers and four USB hubs. The USB controller moves data between main memory and up to six USB connectors. All ports function identically and with the same bandwidth. The SE7505VB2 server board implements four ports on the board.

The baseboard provides three external USB ports on the back of the server board. The triple-stack USB connector is located within the standard ATX I/O panel area next to the keyboard and mouse housing. The USB specification defines the external connectors.

The fourth USB port is optional and can be accessed by cabling from an internal 9-pin connector located on the baseboard to an external USB port located either in front or the rear of a given chassis.

3.2.4.4 Compatibility Interrupt Control

The ICH4 provides the functionality of two 82C59 PIC devices for ISA-compatible interrupt handling.

3.2.4.5 APIC

The ICH4 integrates an I/O APIC capability with 24 interrupts.

3.2.4.6 General Purpose Input and Output Pins

The ICH4 provides a number of general purpose input and output pins. Many of these pins have alternate functions, and thus all are not available. The following table lists the GPI and GPO pins used on the board and gives a brief description of their function.

Table 5. ICH4 GPIO Usage Table

Pin Name (Powe Well)	Used As	GPI / GPO / Function	Function Select	Data.	Pin Description
GPI0 / REQA#	BUS P1 Parity	GPI	GPIO:R00h[0]=1 (GPIO)	PM:R2Eh[0]	1: Normal
(Core)	DETECT		(GPIO:R04h[0] always = 1)		0: SMI or SCI or
	(P1_PERR#)		GPIO:R2Ch[0]=1 (Active Low)		Wakeup event
GPI1 / REQB#	BUS P2/ICH4 Parity	GPI	GPIO:R00h[1]=1 (GPIO)	PM:R2Eh[1]	1: Normal
(Core)	DETECT		(GPIO:R04h[1] always = 1)		0: SMI or SCI or
	(P2_PERR#)		GPIO:R2Ch[1]=1 (Active Low)		Wakeup Event
GPI2 / PIRQE# (Core)	PIRQ_E		GPIO:R00h[2]=0 (PIRQ_E)		
GPI3 / PIRQF# (Core)	PIRQ_F		GPIO:R00h[3]=0 (PIRQ_F)		
GPI4 / PIRQG# (Core)	PIRQ_G		GPIO:R00h[4]=0 (PIRQ_G)		
GPI5 / PIRQH# (Core)	PIRQ_H		GPIO:R00h[5]=0 (PIRQ_H)		
GPI6	IDE ATA66/100	GPI	(GPIO:R04h[6] always = 1)	PM:R2Eh[6]	1: ATA33
(Core)	Detect (IDES_DET)		GPIO:R2Ch[6]=0 (Active High)		0: ATA66/100
GPI7	IDE ATA66/100	GPI	(GPIO:R04h[7] always = 1)	PM:R2Eh[7]	1: ATA33
(Core)	Detect (IDEP_DET)		GPIO:R2Ch[7]=0 (Active High)		0: ATA66/100
GPI8	CPU_HOT#	GPI	(GPIO:R04h[8] always = 1)	PM:R2Eh[8]	1: Normal
(Resume)			GPIO:R2Ch[8]=1 (Active Low)		0: SMI or SCI or Wakeup Event
GPI9 ~ GPI10					N/A
GPI11	NC	GPI	GPIO:R00h[11]=1 (GPIO)	PM:R2Eh[11]	
(Resume)			(GPIO:R04h[11] always = 1)		
			GPIO:R2Ch[11]=0 (Active High)		

Pin Name (Powe Well)	Used As	GPI / GPO / Function	Function Select	Data.	Pin Description
GPI12 (Resume)	Overtemperature shutdown for CPU 1 & 2	GPI	(GPIO:R04h[12] always = 1) GPIO:R2Ch[12]=0 (Active High)	PM:R2Eh[12]	
GPI13 (Resume)		GPI	(GPIO:R04h[13] always = 1) GPIO:R2Ch[13]=1 (Active Low)	PM:R2Eh[13]	NC
GPI14 ~ GPI15					N/A
GPO16 / GNTA# (Core)	N/C	GPO	GPIO:R00h[16]=1 (GPIO) (GPIO:R04h[16] always = 0)	GPIO:R0Ch[16]	TTL Driver Output
GPO17 / GNTB# (Core)	N/C	GPO	GPIO:R00h[17]=1 (GPIO) (GPIO:R04h[16] always = 0)	GPIO:R0Ch[17]	TTL Driver Output
GPO18:19 (Core)	N/C	GPO	GPIO:R18h[18:19] for Blinking (GPIO:R04h[18:19] always = 0)	GPIO:R0Ch[18:19]	TTL Driver Output
GPO20:23 (Core)	N/C	GPO	(GPIO:R04h[18:23] always = 0)	GPIO:R0Ch[18:23]	TTL Driver Output
GPIO24 (Resume)	N/C	GPO	GPIO:R04h[24] = 0	GPIO:R0Ch[24]	TTL Driver Output
GPIO25 (Resume)	CPU1 SKTOCC#	GPI	GPIO:R04h[25] = 1 GPIO:R0Ch[25]=0(Active Low)	GPIO:R0Ch[25]	
GPIO26					N/A
GPIO27 (Resume)	NC	GPI	GPIO:R04h[27] = 1 GPIO:R0Ch[27]=0 (Active Low)	GPIO:R0Ch[27]	
GPIO28 (Resume)	NC	GPI	GPIO:R04h[28] = 1 GPIO:R0Ch[28]=0 (Active Low)	GPIO:R0Ch[28]	
GPIO29:31					N/A
GPIO32 / USBLED_A# (Core)	NC	GPI	GPIO:R30h[0]=1 GPIO:R34h[0]=1	GPIO:R38h[0]	0: present 1: non-present
GPIO33 / USBLED_B# (Core)	CPU2_SKTOCC#	GPI	GPIO:R30h[1]=1 GPIO:R34h[1]=1	GPIO:R38h[1]	0: present 1: non-present
GPIO34 / USBLED_C# (Core)	CPU1_604#	GPI	GPIO:R30h[2]=1 GPIO:R34h[2]=1	GPIO:R38h[2]	0: CPU1 w/604 1: CPU1 w/603
GPIO35 / USBLED_D# (Core)	CPU2_604#	GPI	GPIO:R30h[3]=1 GPIO:R34h[3]=1	GPIO:R38h[3]	0: CPU2 w/604 1: CPU2 w/603
GPIO36 / USBLED_E# (Core)	NC	GPO	GPIO:R30h[4]=1 GPIO:R34h[4]=0	GPIO:R38h[4]	0:Disabled 1:Enable

Pin Name (Powe Well)	Used As	GPI / GPO / Function	Function Select	Data.	Pin Description
GPIO37 /	NC	GPO	GPIO:R30h[5]=1	GPIO:R38h[5]	0:Disabled
USBLED_F# (Core)			GPIO:R34h[5]=0		1:Enable
GPIO38 /	RASERR#	GPI	GPIO:R30h[6]=1	GPIO:R38h[5]	0: Disabled
USBLED_G# (Core)			GPIO:R34h[6]=1		1: Enabled
GPIO39 /	PWR_Alert#	GPI	GPIO:R30h[7]=1b	GPIO:R38h[7]	
USBLED_H#			GPIO:R34h[7]=1b		
GPIO40 /	AGP_PRST#2 (bit2)	GPI	GPIO:R30h[8]=1b	GPIO:R38h[8]	
USBLED_I#			GPIO:R34h[8]=1b		
GPIO41 /	AGP_PRST#1 (bit1)	GPI	GPIO:R30h[9]=1b	GPIO:R38h[9]	
USBLEDJ			GPIO:R34h[9]=1b		
GPIO42 /	DIS_NIC1	GPO	GPIO:R30h[10]=1b	GPIO:R38h[10]	0: Disabled
USBLED_K# (Core)			GPIO:R34h[10]=0b		1: Enabled
GPIO43 /	NC	GPO	GPIO:R30h[11]=1b	GPIO:R38h[11]	
USBLED_L# (Core)			GPIO:R34h[11]=0b		

3.2.4.7 Power Management

One of the embedded functions of the ICH4 is a power management controller. This is used to implement ACPI-compliant power management features. The baseboard does support sleep states S0, S1, S4, and S5.

3.3 Super I/O

The Winbond 83627HF sIO device contains all of the necessary circuitry to control two serial ports, one parallel port, floppy disk, PS/2-compatible keyboard and mouse and hardware monitor controller. The baseboard implements the following features:

- GPIOs
- Two serial ports
- Floppy
- Keyboard and mouse
- Local hardware monitoring
- Wake up control

3.3.1 GPIOs

The sIO provides a number of general-purpose input/output pins that the baseboard utilizes. The following table identifies the pin and the signal name used in the schematic:

Pin GPI/GPO Name Used as **Function Select** Data Description Pin No. **Function** GPIO12 0: Clear Password CR2A<7>=1 & CR2A<4>=1 & LD7 CLRPAS# **GPI** LD7[F1h]<2> (Pin 126) [F0h]<2>=1 1: Normal GPIO13 CR2A<7>=1 & CR2A<3>=1 & LD7 FanSlct1# **GPO** LD7[F1h]<3> (Pin 125) [F0h]<3>=0 GPIO15 FanSlct2# **GPO** (Pin 123) GPIO17 0: Factory mode MAG_jmpr GPI CR2A<7>=1 & LD7 [F0h]<7>=1 LD7[F1h]<7> (Pin 121) 1: normal GPIO20 0: Recovery mode RECRYMD# GPI CR2A<0>=1 & LD8[F0h]<0>=1 LD8[F1h]<0> (Pin 119) 1:Normal 0: Flash ROM **GPIO25** Write En Flash_EN# **GPO** LD8[F1h]<5> CR2B<3>=1 & LD8[F0h]<5>=0 (Pin 88) 1: normal 0: Power button **GPIO26** Disabled Btn dsabl# **GPO** CR2B<2>=1 & LD8[F0h]<6>=0 LD8[F1h]<6> (Pin 87) 1: normal GPIO35 Blink LED **SUSLED** CR29h<7>=0 (Pin 64)

Table 6. Super I/O GPIO Usage Table

3.3.2 Serial Ports

The board provides two serial ports, an external serial port, and an internal serial header. The following sections provide details on the use of the serial ports.

3.3.2.1 Serial A

Serial A is a standard DB9 interface located at the rear I/O panel of the server board, to the left of the video connector below the parallel port connector. Serial A is designated by as "Serial A" on the silkscreen. The reference designator is J8A1.

3.3.2.2 Serial B

Serial B is an optional port, accessed through a 9-pin internal header (J1J2). A standard DH-10 to DB9 cable can be used to direct serial B to an external connector on any given chassis. The serial B interface follows the standard RS232 pinout. The baseboard has a "Serial B" silkscreen label next to the connector and is located below the floppy connector.

3.3.2.3 Floppy Disk Controller

The floppy disk controller (FDC) in the sIO is functionally compatible with floppy disk controllers in the DP8473 and N844077. All FDC functions are integrated into the sIO including analog data separator and 16-byte FIFO. The baseboard provides a standard 34-pin interface for the floppy disk controller.

3.3.2.4 Keyboard and Mouse

Two external PS/2 ports, located on the back of the baseboard, are provided to access the keyboard or mouse functions. The two ports are interchangeable and will automatically detect and configure a keyboard or mouse plugged into either port.

3.3.2.5 Wake-up Control

The sIO contains functionality that allows various events to control the power-on and power-off the system.

3.3.3 BIOS Flash

The board incorporates an Intel[®] N82802AC (FWH8) flash memory component. The N82802AC is a high-performance 8-megabit memory component that provides 1024K x 8 of BIOS and non-volatile storage space. The flash device is connected through the LPC Bus from the ICH4 from the sIO.

4. Clock Generation and Distribution

All buses on the Intel Server Board SE7505VB2 operate using synchronous clocks. Clock synthesizer/driver circuitry on the baseboard generates clock frequencies and voltage levels as required, including the following:

- 100 MHz at 3.3 V logic levels. For Processor 0, Processor 1, Debug Port and MCH.
- 66 MHz at 3.3 V logic levels: For MCH, ICH4, AGP, and P64H2
- 48 MHz at 3.3V logic levels: For ICH4
- 33 MHz at 3.3V logic levels: For ICH4, PCI Connector, sIO and FWH
- 14.318 MHz at 2.5 V logic levels: For ICH4 and sIO

The following figure illustrates clock generation and distribution on the board.

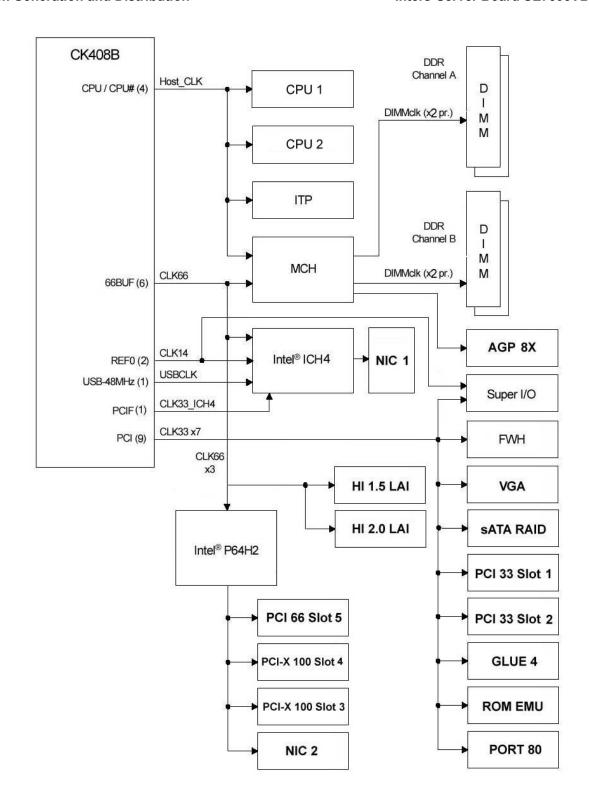


Figure 4. SE7505VB2 Clock Distribution Diagram

5. PCI I/O Subsystem

5.1 PCI Subsystem

The primary I/O bus for the server board SE7505VB2 is PCI, with three independent PCI bus segments. The PCI buses comply with the PCI Local Bus Specification, Rev 2.3. The P32-A bus segment is directed through the ICH4 while the two 64-bit segments, P64-B and P64-C, are directed through the P64H2 I/O Bridge. The table below lists the characteristics of the three PCI bus segments.

PCI Bus Segment PCI I/O Card Slots Voltage Width Speed Type P32-A 5 V 32-bits 33 MHz PCI Two slots, support full-length cards P64-B 3.3 V 64-bits 100 MHz PCI-X Two slots, support full-length cards P64-C 3.3 V 64-bits 66 MHz PCI One slot, supports full-length cards

Table 7. PCI Bus Segment Characteristics

5.1.1 P32-A: 32-bit/33-MHz PCI Subsystem

All 32-bit/33-MHz PCI I/O for the board is directed through the ICH4. The 32-bit/33-MHz PCI segment created by the ICH4 is known as the P32-A segment. The P32-A segment supports the following embedded devices and connectors:

- Serial ATA controller: Silicon Image* 3112A.
- One 10/100 Network Interface Controller: Intel 82550PM Fast Ethernet Controller.
- 2D/3D Graphics Accelerator: ATI Rage XL Video Controller

The Serial ATA controller and the NIC will each be allocated a GPIO to disable the device. The video controller will be disabled when an off-board video device is detected in either the AGP or PCI bus segments

5.1.1.1 Device IDs (IDSEL)

Each device under the PCI hub bridge has its IDSEL signal connected to one bit of AD[31:16], which acts as a chip select on the PCI bus segment in configuration cycles. This determines a unique PCI device ID value for use in configuration cycles. The following table shows the bit to which each IDSEL signal is attached for P32-A devices and the corresponding device description.

IDSEL Value	Device
16	PCI 33MHz Slot 1
17	PCI 33MHz Slot 2
18	ATI Rage XL Video Controller
19	Intel® 82550PM Fast Ethernet Controller (NIC1)
20	SATA controller Silicon Image 3112A

Table 8. P32-A Configuration IDs

5.1.1.2 P32-A Arbitration

P32-A supports six PCI devices: the ICH4 and five PCI bus masters (one NIC, one sATA RAID controller, two PCI slots and one ATI Rage XL video controller). All PCI masters must arbitrate for PCI access, using resources supplied by the ICH4. The host bridge PCI interface (ICH4) arbitration lines REQx* and GNTx* are a special case in that they are internal to the host bridge. The following table defines the arbitration connections.

Baseboard SignalsDeviceP32_REQ0*/P32_GNT0*PCI 33MHz Slot 1P32_REQ1*/P32_GNT1*PCI 33MHz Slot 2P32_REQ2*/P32_GNT2*ATI Rage XL video controllerP32_REQ3*/P32_GNT3*Intel 82550PM Fast Ethernet Controller (NIC1)P32_REQ4*/P32_GNT4*Silicon Image Serial ATA Controller

Table 9. P32-A Arbitration Connections

5.1.2 P64-B and P64-C: 64-bit/100- or 66-MHz PCI Subsystem

Two peer 64-bit bus segments are directed through the P64H2 I/O Bridge. The first PCI segment, P64-B, provides two 3.3V 64-bit PCI-X slots capable of 100 MHz operation and support full-length PCI cards.

The second PCI segment, P64-C, provides a single 3.3V 64-bit PCI slot operating at 66 MHz. This segment supports full-length PCI cards. P64-C also has an embedded Intel 82540EM fast Ethernet gigabit controller.

5.1.2.1 Device IDs (IDSEL)

Each device under the PCI hub bridge has its IDSEL signal connected to one bit of AD[31:16], which acts as a chip select on the PCI bus segment in configuration cycles. This determines a unique PCI device ID value for use in configuration cycles. The following table shows the bit to which each IDSEL signal is attached for P64-B devices and corresponding device description.

Table 10. P64-B Configuration IDs

IDSEL Value	Device
17	PCI-X 100MHz Slot 4
18	PCI-X 100MHz Slot 3

Table 11. P64-C Configuration IDs

IDSEL Value	Device
17	PCI 66MHz Slot 5
18	Intel® 82540EM Fast Ethernet Controller (NIC2)

5.1.2.2 P64-B Arbitration

P64-B supports three PCI masters: two PCI-X slots and the P64H2. All PCI masters must arbitrate for PCI access using resources supplied by the P64H2. The host bridge PCI interface (P64H2) arbitration lines REQx* and GNTx* are a special case in that they are internal to the host bridge. The following table defines the arbitration connections.

Table 12. P64-B Arbitration Connections

Baseboard Signals	Device
P64_P_REQ0*/P64_P_GNT0*	PCI-X 100MHz Slot 4
P64_P_REQ1*/P64_P_GNT1*	PCI-X 100MHz Slot 3

5.1.2.3 P64-C Arbitration

P64-C supports three PCI masters: one PCI slot, Intel 82540EM controller and the P64H2. All PCI masters must arbitrate for PCI access, using resources supplied by the P64H2. The host bridge PCI interface (P64H2) arbitration lines REQx* and GNTx* are a special case in that they are internal to the host bridge. The following table defines the arbitration connections.

Table 13. P64-C Arbitration Connections

Baseboard Signals	Device
P64_S_REQ0*/P64_S_GNT0*	PCI 66MHz Slot 5
P64_S_REQ1*/P64_S_GNT1*	Intel 82540EM Fast Ethenet Controller (NIC 2)

5.2 Serial ATA Controller

The board provides an embedded dual port Serial ATA controller through the use of the Silicon Image* 3112A ASIC. The Silicon Image 3112A provides a single 32-bit / 33-MHz PCI bus master interface as a multifunction device, packaged in a 128-pin PQFP. It supports two modes: base mode and RAID mode.

The Silicon Image 3112A controller supports the following features:

- Automatically selects highest available transfer speed for all devices
- Supports:
 - UDMA up to 150MB/second
 - All UDMA and PIO modes
 - Up to two SATA devices
 - ACPI and ATA/ATAPI6
- RAID 0 and 1¹
- On-line mirror rebuilding
- RAID set accommodates multiple size HDDs
- HDDs function normally when not in RAID sets
- Adjustable stripe size for RAID 0

¹ RAID functionality available under most operating systems. Check the SE7505VB2 support website at http://support.intel.com/support/motherboards/server/se7505vb2 for details.

The baseboard ships with the Silicon Image controller set to Base ATA mode. To switch the controller to RAID mode, a utility needs to be downloaded from the SE7505VB2 support website or run from the resource CD. This utility switches the controller from one mode to the other. Appropriate drivers need to be loaded, depending on the mode the controller is set to.

This method was chosen over a BIOS F2 setup switch to allow the controller settings to be maintained in the event of a Clear CMOS operation. If the RAID drivers were loaded and a Clear CMOS operation was executed, but the device was not reset to RAID mode, the operating system would not load. Refer to the SE7505VB2 support website for details on which operating systems support RAID mode.

Note: The onboard NICs need to be enabled for the ATA mode/RAID mode utility to properly program the device. The utility toggles the Sub-System ID (SSID) in the NIC EEPROM between two different values. The BIOS will load the appropriate Silicon Image Option ROM based on the SSID that is set in the NIC EEPROM. The NICs need to be enabled for the BIOS to know which SSID is set and subsequently which option ROM to load.

When in RAID mode, the Silicon Image controller can support the following RAID levels:

RAID Level	Performance	Capacity	# of Drives
RAID 0 (Striping)	Highest	Number of drives multiplied by the smallest drive size	2
RAID 1 (Mirroring)	Normal	50% min	2

Table 14. sATA RAID Level

RAID 0 configurations are primarily used for high performance applications, as it doubles the sustained transfer rate of its drives. RAID 1 configurations are primarily used for data protection. RAID 1 creates an identical backup of the primary drive to a secondary drive. Whenever a disk write is performed, the controller sends data simultaneously to a second drive located on a different data channel.

5.3 Video Controller

The baseboard provides an ATI Rage XL PCI graphics accelerator, along with 8 MB of video SDRAM and support circuitry for an embedded SVGA video subsystem. The ATI Rage XL chip contains a SVGA video controller, clock generator, 2D and 3D engine, and RAMDAC in a 272-pin PBGA. One 2Mx32 SDRAM chip provides 8 MB of video memory.

The SVGA subsystem supports a variety of modes, up to 1600×1200 resolution in 8/16/24/32 bpp modes under 2D, and up to 1024×768 resolution in 8/16/24/32 bpp modes under 3D. It supports both CRT and LCD monitors with up to 100 Hz vertical refresh rate.

The baseboard provides a standard 15-pin VGA connector at the rear of the system, in the standard ATX I/O opening area. The video controller disabled by default in BIOS Setup when an off-board video adapter is detected in either the AGP or PCI slots. Optionally, the video controller can be set to support dual monitor mode when an off-board AGP adapter is detected. The onboard controller would act as the primary video controller and the AGP adapter becomes the secondary adapter under an operating system that supports this functionality.

5.3.1 Video Modes

The ATI Rage XL chip supports all standard IBM VGA modes. The following table shows the 2D/3D modes supported for both CRT and LCD. The table specifies the minimum memory requirement for various display resolution, refresh rates and color depths.

Table 15. Video Modes

2D Mode	Refresh Rate (Hz)	SE7505VB2 2D Video Mode Support					
		8 bpp	8 bpp 16 bpp		32 bpp		
640x480	60, 72, 75, 90, 100	Supported	Supported	Supported	Supported		
800x600	60, 70, 75, 90, 100	Supported	Supported	Supported	Supported		
1024x768	60, 72, 75, 90, 100	Supported	Supported	Supported	Supported		
1280x1024	43, 60	Supported	Supported	Supported	Supported		
1280x1024	70, 72	Supported	_	Supported	Supported		
1600x1200	60, 66	Supported	Supported	Supported	Supported		
1600x1200	76, 85	Supported	Supported	Supported	_		
3D Mode	Refresh Rate (Hz)	SE7505VE	32 3D Video Mode S	Support with Z Buff	er Enabled		
640x480	60,72,75,90,100	Supported	Supported	Supported	Supported		
800x600	60,70,75,90,100	Supported	Supported	Supported	Supported		
1024x768	60,72,75,90,100	Supported	Supported	Supported	Supported		
1280x1024	43,60,70,72	Supported	Supported	_	_		
1600x1200	60,66,76,85	Supported	_	_	_		
3D Mode	Refresh Rate (Hz)	SE7505VB	2 3D Video Mode S	Support with Z Buff	er Disabled		
640x480	60,72,75,90,100	Supported	Supported	Supported	Supported		
800x600	60,70,75,90,100	Supported	Supported	Supported	Supported		
1024x768	60,72,75,90,100	Supported	Supported	Supported	Supported		
1280x1024	43,60,70,72	Supported	Supported	Supported	_		
1600x1200	60,66,76,85	Supported	Supported	_	_		

5.3.2 Video Memory Interface

The memory controller subsystem of the ATI Rage XL arbitrates requests from direct memory interface, the VGA graphics controller, the drawing coprocessor, the display controller, the video scalar, and hardware cursor. Requests are serviced in a way that ensures display integrity and maximum CPU/coprocessor drawing performance.

The board supports an 8 MB (512Kx32bitx4 Banks) SDRAM device for video memory.

5.3.3 Host Bus Interface

The ATI Rage XL supports a PCI 33 MHz bus. The following diagram shows the signals for the PCI interface:

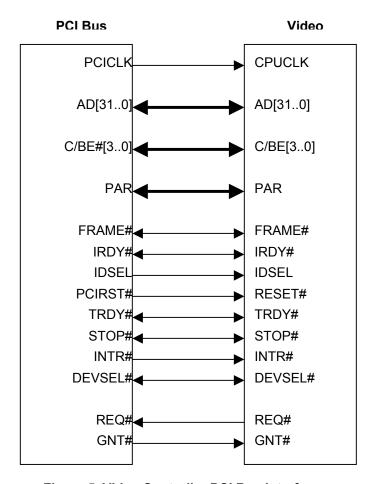


Figure 5. Video Controller PCI Bus Interface

5.4 Network Interface Controller (NIC)

The server board SE7505VB2 supports one 10Base-T/100Base-TX network interface controller (NIC) based on the Intel 82550PM controller (NIC 1) and one gigabit network interface controller based on the Intel 82540EM controller (NIC 2).

The 82550PM is a highly integrated PCI LAN controller in a thin BGA 15 mm² package. The controller's baseline functionality is equivalent to that of the Intel 82559 with the addition of Alert-on-LAN functionality. The 82550PM supports the following features:

- Glueless 32-bit PCI, CardBus master interface (Direct Drive of Bus), compatible with PCI local Bus Specification, Revision 2.2.
- Integrated IEEE 802.3 10Base-T and 100Base-TX compatible PHY
- IEEE 820.3u auto-negotiation support
- Full duplex support at both 10 Mbps and 100 Mbps operation
- Integrated UNDI ROM support
- MDI/MDI-X and HWI support
- Low power +3.3 V device

The 82540EM is a single, compact component with integrated gigabit Ethernet MAC and PHY layer functions and is packaged in a 15mm² TFBGA. The baseboard supports independent disabling of the two NIC controllers using the BIOS setup menu. The 82540EM supports the following features:

- Support for the 33/66MHz bus segment
- Integrated 10/100/1000 Mb/s full and half duplex operation
- SMBUS. ASF 1.0, ACPI, WoL and PXE management functions
- Compliant w/ PCI Power Management v1.1 and ACPI v2.0

5.4.1 NIC Connector and Status LEDs

The NICs drive two LEDs located on each network interface connector.

For the NIC 1 connector, the green LED indicates network connection when on, and Transmit/Receive activity when blinking. The green LED indicates 100-Mbps operation when lit, and 10-Mbps when off.

For the NIC 2 connector, the amber LED indicates network connection when on, and Transmit/Receive activity when blinking. The green LED indicates 1000-Mbps operation when lit, the orange LED indicates 100-Mbps operation when lit and 10-Mbps when off.

5.5 Interrupt Routing

The board interrupt architecture accommodates both PC-compatible PIC mode and APIC mode interrupts through use of the integrated I/O APICs in the ICH4.

5.5.1 Legacy Interrupt Routing

For PC-compatible mode, the ICH4 provides two 82C59-compatible interrupt controllers. The two controllers are cascaded with interrupt levels 8-15 entering on level 2 of the primary interrupt controller (standard PC configuration). A single interrupt signal is presented to the processors, to which only one processor will respond for servicing. The ICH4 contains configuration registers that define which interrupt source logically maps to I/O APIC INTx pins.

The ICH4 handles both PCI and IRQ interrupts. The ICH4 translates these to the APIC bus. The numbers in the table below indicate the ICH4 PCI interrupt input pin to which the associated device interrupt (INTA, INTB, INTC, INTD) is connected. The ICH4 I/O APIC exists on the I/O APIC bus with the processors.

Interrupt	INT A	INT B	INT C	INT D	
AGPA#	ICH4_PIRQA#				
AGPB#	ICH4_PIRQB#				
VGA#	ICH4_PIRQB#				
sATA#	ICH4_PIRQD#				
NIC1#	ICH4-PIRQC#				
NIC2#	P1-IRQ4#				
P64H2-A# [P1/P2]	ICH4_PIRQE#				
P64-C Slot 5	P1_IRQ0#	P1_IRQ1#	P1_IRQ2#	P1_IRQ3#	
P64-B Slot 4	P2_IRQ0#	P2_IRQ1#	P2_IRQ2#	P2_IRQ3#	
P64-B Slot 3	P2_IRQ4#	P2_IRQ5#	P2_IRQ6#	P2_IRQ7#	
P32-A Slot 2	ICH4_PIRQG#	ICH4_PIRQF#	ICH4_PIRQE#	ICH4_PIRQH#	
P32-A Slot 1	ICH4_PIRQF#	ICH4_PIRQG#	ICH4_PIRQH#	ICH4_PIRQE#	

Table 16. PCI Interrupt Routing/Sharing

5.5.2 APIC Interrupt Routing

For APIC mode, the baseboard interrupt architecture incorporates three Intel[®] I/O APIC devices to manage and broadcast interrupts to local APICs in each processor. The Intel I/O APICs monitor each interrupt on each PCI device, including PCI slots in addition to the ISA compatibility interrupts IRQ(0-15).

When an interrupt occurs, a message corresponding to the interrupt is sent across a three-wire serial interface to the local APICs. The APIC bus minimizes interrupt latency time for compatibility interrupt sources. The I/O APICs can also supply greater than 16 interrupt levels to the processor(s). This APIC bus consists of an APIC clock and two bidirectional data lines.

5.5.2.1 Legacy Interrupt Sources

The table below recommends the logical interrupt mapping of interrupt sources on the board. The actual interrupt map is defined using configuration registers in the ICH4.

ISA Interrupt Description INTR Processor interrupt. NMI NMI to processor. IRQ0 System timer IRQ1 Keyboard interrupt. IRQ2 Slave PIC IRQ3 Serial port 1 or 2 interrupt from SIO device, user-configurable. Serial port 1 or 2 interrupt from SIO device, user-configurable. IRQ4 IRQ5 Parallel Port / Generic IRQ6 Floppy disk. IRQ7 Parallel Port / Generic Active low RTC interrupt. IRQ8 L IRQ9 SCI* IRQ10 Generic IRQ11 Generic IRQ12 Mouse interrupt. IRQ13 Floaty processor. IRQ14 Compatibility IDE interrupt from primary channel IDE devices 0 and 1. IRQ15 Secondary IDE Cable SMI* System Management Interrupt. General purpose indicator sourced by the ICH4 to the processors.

Table 17. Interrupt Definitions

5.5.3 Serialized IRQ Support

The SE7505VB2 server board supports a serialized interrupt delivery mechanism. Serialized Interrupt Requests (SERIRQ) consists of a start frame, a minimum of 17 IRQ / data channels, and a stop frame. Any slave device in the quiet mode may initiate the start frame. While in the continuous mode, the start frame is initiated by the host controller.

5.5.4 IRQ Scan for PCIIRQ

The IRQ / data frame structure includes the ability to handle up to 32 sampling channels with the standard implementation using the minimum 17 sampling channels. The board has an external PCI interrupt serializer for PCIIRQ scan mechanism of ICH4 to support 16 PCIIRQs.

5.6 PCI Error Handling

The PCI bus defines two error pins, PERR# and SERR#, for reporting PCI parity errors and system errors, respectively. In the case of PERR#, the PCI bus master has the option to retry the offending transaction, or to report it using SERR#. All other PCI-related errors are reported by SERR#. SERR# is routed to NMI if enabled by BIOS.

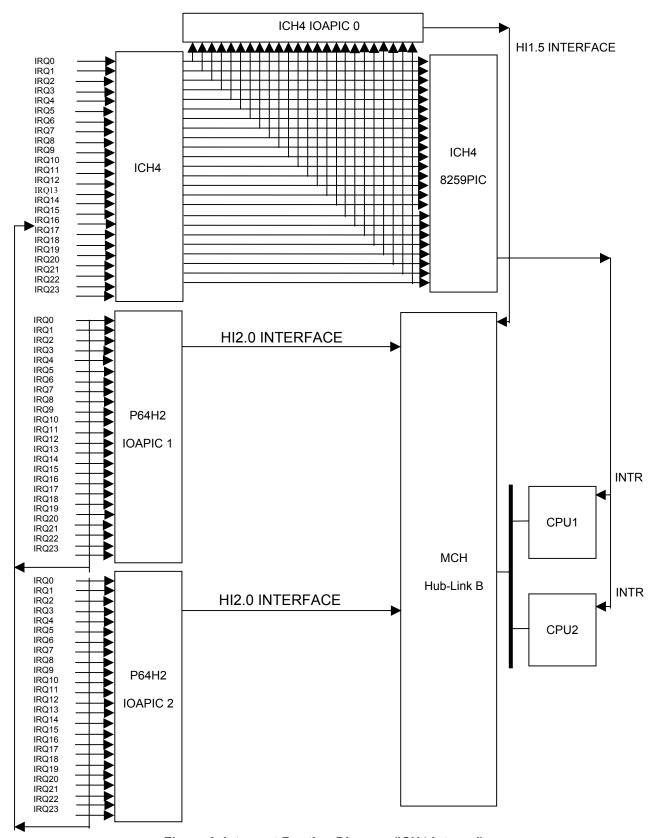


Figure 6. Interrupt Routing Diagram (ICH4 Internal)

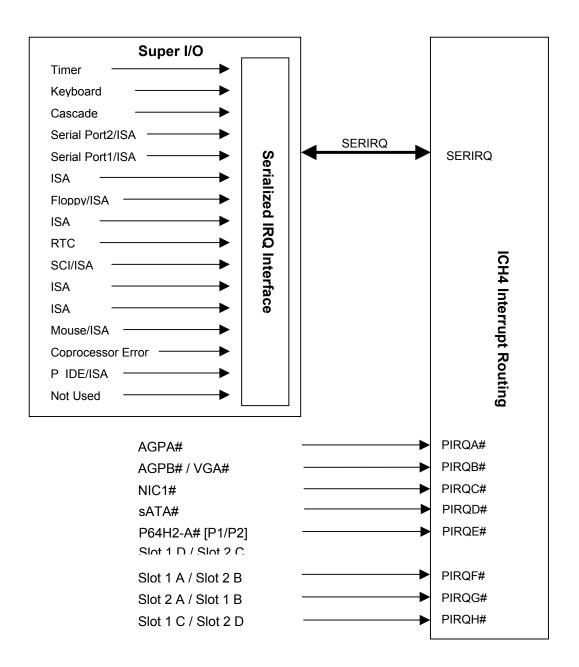
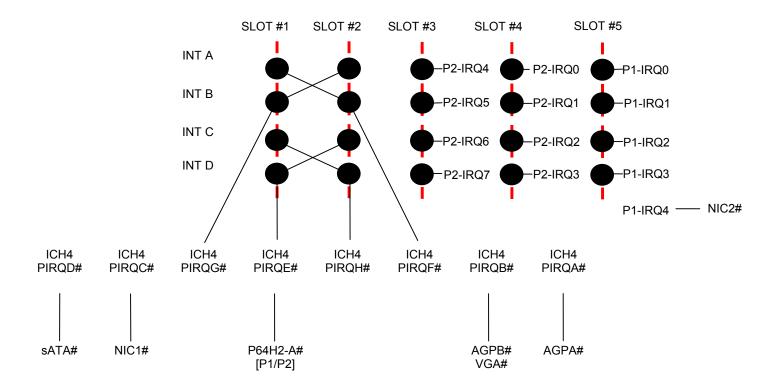


Figure 7. Interrupt Routing Diagram



Note: P1 is P64H2 PCI-bus B, P2 is P64H2 PCI-bus C

Figure 8. The Board PCI Interrupt Mapping Diagram

6. Hardware Monitoring

6.1 Monitored Components

The Intel Server Board SE7505VB2 has an integrated Winbond* Heceta chip that is responsible for hardware monitoring. The Winbond Heceta chip provides basic server hardware monitoring which alerts a system administrator if a hardware problem occurs on the board. The retail boxed board ships with a copy of LANDesk* Client Manager, which can monitor the management bus for these alerts and help administrators identify a problem on the board. Below is a table of monitored headers and sensors on the board.

Table 18. Monitored Components

Item		Description			
Voltage	Vcpu	Monitors processor voltage	(sIO)		
	1.8V	Monitors +1.8V	(sIO)		
	3.3V	Monitors +3.3V	(sIO)		
	5V	Monitors 5VSB (Internal)	(sIO)		
	SB3V Monitors +12Vin				
	ENG12V	Monitors –12Vin (should be same as 12V @ Power-Supply)	(sIO)		
	2.5V	Monitors –5V	(sIO)		
	Vbat	Monitors battery voltage	(sIO)		
	SB5V	Monitors 5VSB	(sIO)		
Fan Speed	PWM1	Controls system fans	(sIO)		
		CPU fans (invariable speed)	(sIO)		
	TACH1	Monitors system fan 1 (front)	(sIO)		
	TACH2	Monitors system fan 2 (front)	(sIO)		
	TACH3	Monitors system fan 4 (rear)	(sIO)		
	TACH4	Monitors system fan 3 (rear)	(sIO)		
	TACH5	Monitors CPU fan 2	(sIO)		
	TACH6	Monitors CPU fan 1	(sIO)		
Temperature	CPU0	Monitors primary processor temperature	(sIO)		
	CPU1	Monitors secondary processor temperature	(sIO)		
	Ambient	Monitors Ambient temperature	(sIO)		

The LANDesk Client Manager software and a white paper that provides more information on using LDCM are available on the *Intel® Server Board SE7505VB2 Resource CD*.

6.2 Fan Speed Control

The Winbond W83627HF can be used to monitor several critical hardware parameters of the system, including power supply voltages, fan speeds, and temperatures. Fan speed control is to use the Pulse Width Modulation (PWM) technical knowledge to control the Fan's RPM.

The following shows the temperature range vs. output voltage for controlling the speed of all system fans.

Temperature Range	Output Voltage
Temperature >= 37°C	12V
33°C <= temperature < 37°C	10.5V
30°C <= temperature < 33°C	7.5V
Temperature < 30°C	6.2V

The following is to setup fan count limit for rear and front system fans and CPU fans.

Voltage	Duty Cycle	Rear System Fan (Delta 8012)	Rear System Fan Limit (~70%)	Rear System Fan Count Limit	
6.2V	26h	1750 RPM	1222 RPM	8Ah	
7.5V	27h	2300 RPM	1607 RPM	69h	
10.5V	2Ah	3250 RPM	2250 RPM	4Bh	
12.0V	2Fh	3700 RPM	2556 RPM	42h	

Voltage	Duty Cycle	Front System Fan (NMB)	Front System Fan Limit (~70%)	Front System Fan Count Limit	
6.2V	26h	2650 RPM	1854 RPM	5Bh	
7.5V	27h	3100 RPM	2163 RPM	4Eh	
10.5V	2Ah	4000 RPM	2766 RPM	3Dh	
12.0V	2Fh	4300 RPM	2960 RPM	39h	

CPU Fan Speed Limit	CPU Fan Count Limit			
2766 RPM	3Dh			

6.3 Chassis Intrusion

The SE7505VB2 server board supports a chassis security feature that detects if the chassis cover is removed. For the chassis intrusion circuit to function, the chassis' power supply must be connected to AC power. The security feature uses a mechanical switch on the chassis that attaches to the chassis intrusion connector. When the chassis cover is removed the mechanical switch is in the closed position.

Below is a diagram explaining what the Winbond W83627HF controller monitors on the baseboard and how the monitoring is accomplished.

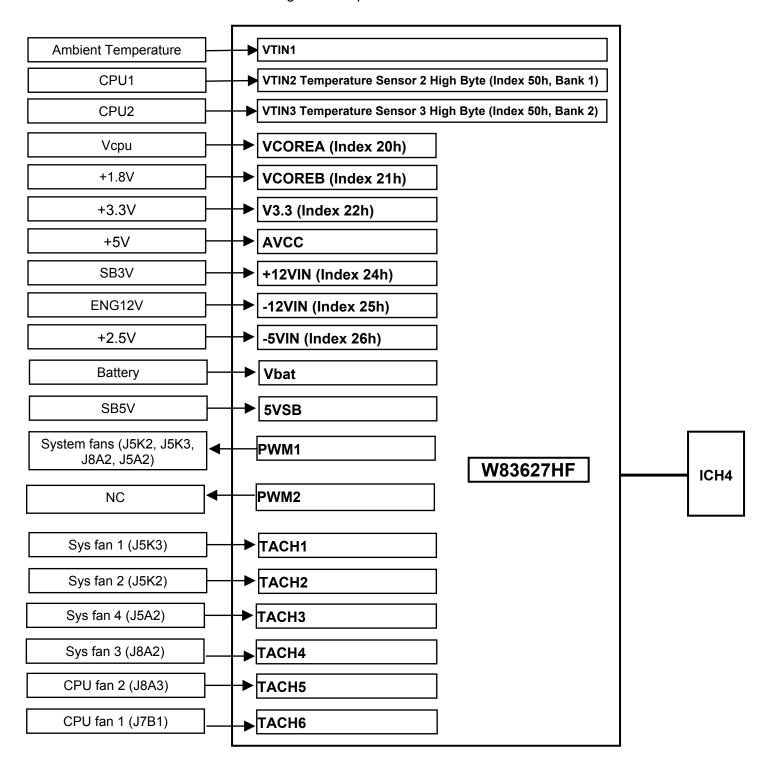


Figure 9. Hardware Monitoring

7. SE7505VB2 ACPI Implementation

7.1 ACPI

An ACPI-aware operating system generates an SMI to request that the system be switched into ACPI mode. The BIOS responds to enable ACPI mode. The system automatically returns to legacy mode upon hard reset or power-on reset.

The SE7505VB2 platform supports S0, S1, S4, and S5 states. When the system is operating in ACPI mode, the OS retains control of the system and OS policy determines the entry methods and wake up sources for each sleep state

Note: Sleep entry and wake up event capabilities are provided by the hardware but are enabled by the operating system.

S0 Sleep State The S0 sleep state is when everything is on. This is the state that no sleep is enabled.

S1 Sleep State The S1 sleep state is a low wake-up latency sleep state. In this state, no system context is lost (Processor or chipset). The system context is

maintained by the hardware.

S4 Sleep State The S4 Non-Volatile Sleep state (NVS) is a special global system state that allows system context to be saved and restored (relatively slowly) when

power is lost to the baseboard. If the system has been commanded to enter the S4 sleep state, the operating system will write the system context to a

non-volatile storage file and leave appropriate context markers.

S5 Sleep State The S5 sleep state is similar to the S4 sleep state except the operating

system does not save any context nor enable any devices to wake the system. The system is in the "soft" off state and requires a complete boot

when awakened.

7.1.1 Front Panel Switches

The baseboard supports two front panel buttons:

- Power button
- Reset button

The power button input (SW2#) provides PWRBTN_IN signal to the sIO. The power button input behaves differently depending on whether or not the operating system supports ACPI.

Power Button Off to On: The sIO may be configured to generate wakeup events for several

different system events: Wake on LAN*, PCI Power Management Interrupt, and Real Time Clock Alarm are examples of these events. Since the processors are not executing, the BIOS does not participate in this sequence. The sIO provides ONSTL# signal to the power supply. The ICH4 and receive power good and reset and

then transition to an ON state.

Power Button On to Off

(Legacy):

The ICH4 is configured to generate an SMI due to a power button event. The BIOS services this SMI and sets the state of the

machine in the ICH4 and sIO to the OFF state.

Power Button On to Off

(ACPI):

If an ACPI operating system is loaded, the power button switch generates a request (via SCI) to the OS to shutdown the system. The OS retains control of the system and determines what sleep

state (if any) the system transitions to.

Reset Button: The reset button will generate a hard reset to the system.

NMI Button: The NMI button will force an NMI to the processors.

7.1.2 Wake up Sources (ACPI and Legacy)

The baseboard is capable of wake up from several sources under a non-ACPI configuration, such as when the operating system does not support ACPI. The wake up sources are defined in the following table.

Table 19. Supported Wake Events

Wake Event	Supported via ACPI (by sleep state)	Supported Via Legacy Wake		
Power Button	Always wakes system	Always wakes system		
Ring indicate from serial1	S1, S4, S5	S5		
Ring indicate from serial2	S1, S4, S5	S5		
PME from PCI 32/33	S1, S4, S5	S5		
PME from PCI secondary 64/100	S1, S4, S5	S5		
PME from primary PCI 64/66	S1, S4, S5	S5		
RTC Alarm	S1, S4	No		
Mouse	S1	No		
Keyboard	S1	No		
USB	S1	No		

Under ACPI, the operating system programs the ICH4 and sIO to wake up on the desired event, but in legacy mode, the BIOS enables/disables wake up sources based on an option in BIOS Setup. The operating system or a driver must clear any pending wake up status bits in the associated hardware (such as the Wake on LAN status bit in the LAN application specific integrated circuit (ASIC), or PCI Power Management Event (PME) status bit in a PCI device. The legacy wake up feature is disabled by default.

8. SE7505VB2 Connectors

8.1 Main Power Connector

The main power supply connection is obtained using the 24-pin connector. The following table defines the pin-outs of the connector.

Table 20. Power Connector Pin-out (J9B1)

Color	Signal	Pin	Pin	Signal	Color
Orange	3.3V	13	1	3.3V	Orange
Blue	-12V	14	2	3.3V	Orange
Black	GND	15	3	GND	Black
Green	DC_ON#	16	4	+5V	Red
Black	GND	17	5	GND	Black
Black	GND	18	6	+5V	Red
Black	GND	19	7	GND	Black
White		20	8	PS_GOOD	Gray
Red	+5V	21	9	SB5V	Purple
Red	+5V	22	10	+12V	Yellow
Red	+5V	23	11	+12V	Yellow
Black	GND	24	12	3.3V	Orange

Table 21. Auxiliary Signal Connector (J7K1)

Pin	Signal	Color
1	SCL	Green
2	SDA	Yellow
3	PWR_Alert#	Red
4	GNDsens	Black
5	3.3Vsens	Orange

Table 22. Auxiliary CPU Power Connector Pin-out (J9K1)

Signal	Pin	Pin	Signal
+12ENG	5	1	GND
+12ENG	6	2	GND
+12ENG	7	3	GND
+12ENG	8	4	GND

8.2 Memory Module Connector

The board has four DDR266 DIMM connectors and supports registered ECC DDR modules (Rev 1.0).

Table 23. DIMM Connectors (J9H1, J9J1, J9H2, J9J2)

Pin	Front	Pin		Pin	Front	Pin	Back	Pin	Back		Back
1	VREF	32	A5	62	VDDQ	93	VSS	124	VSS	154	/RAS
2	DQ0	33	DQ24	63	/WE	94	DQ4	125	A6	155	DQ45
3	VSS	34	VSS	64	DQ41	95	DQ5	126	DQ28	156	VDDQ
4	DQ1	35	DQ25	65	/CAS	96	VDDQ	127	DQ29	157	/CS0
5	DQS0	36	DQS3	66	VSS	97	DM0	128	VDDQ	158	*/CS1
6	DQ2	37	A4	67	DQS5	98	DQ6	129	DM3	159	DM5
7	VDD	38	VDD	68	DQ42	99	DQ7	130	A3	160	VSS
8	DQ3	39	DQ26	69	DQ43	100	VSS	131	DQ30	161	DQ46
9	NC	40	DQ27	70	VDD	101	NC	132	VSS	162	DQ47
10	/RESET	41	A2	71	*/CS2	102	NC	133	DQ31	163	*/CS3
11	VSS	42	VSS	72	DQ48	103	*A13	134	CB4	164	VDDQ
12	DQ8	43	A1	73	DQ49	104	VDDQ	135	CB5	165	DQ52
13	DQ9	44	CB0	74	VSS	105	DQ12	136	VDDQ	166	DQ53
14	DQS1	45	CB1	75	*/CK2	106	DQ13	137	CK0	167	NC
15	VDDQ	46	VDD	76	*CK2	107	DM1	138	/CK0	168	VDD
16	*CK1	47	DQS8	77	VDDQ	108	VDD	139	VSS	169	DM6
17	*/CK1	48	A0	78	DQS6	109	DQ14	140	DM8	170	DQ54
18	VSS	49	CB2	79	DQ50	110	DQ15	141	A10	171	DQ55
19	DQ10	50	VSS	80	DQ51	111	*CKE1	142	CB6	172	VDDQ
20	DQ11	51	CB3	81	VSS	112	VDDQ	143	VDDQ	173	NC
21	CKE0	52	BA1	82	VDDID	113	*BA2	144	CB7	174	DQ60
22	VDDQ	KEY	•	83	DQ56	114	DQ20	KEY		175	DQ61
23	DQ16	53	DQ32	84	DQ57	115	A12	145	VSS	176	VSS
24	DQ17	54	VDDQ	85	VDD	116	VSS	146	DQ36	177	DM7
25	DQS2	55	DQ33	86	DQS7	117	DQ21	147	DQ37	178	DQ62
26	VSS	56	DQS4	87	DQ58	118	A11	148	VDD	179	DQ63
27	A9	57	DQ34	88	DQ59	119	DM2	149	DM4	180	VDDQ
28	DQ18	58	VSS	89	VSS	120	VDD	150	DQ38	181	SA0
29	A7	59	BA0	90	NC	121	DQ22	151	DQ39	182	SA1
30	VDDQ	60	DQ35	91	SDA	122	A8	152	VSS	183	SA2
31	DQ19	61	DQ40	92	SCL	123	DQ23	153	DQ44	184	VDDSPD

Note:

^{*} These pins are not used in this module.

8.3 Processor Socket

The board has two Socket 604 processor sockets. The following table provides the processor socket pin numbers and pin names:

Table 24. Socket 604 Processor Socket Pin-out (U8C1, U5C1)

Pin No	Pin Name	Pin No	Pin Name						
A1	Reserved	D29	VCC	K3	VCC	T29	VSS	AB3 ²	BSEL1
A2	VCC	D30	VSS	K4	VSS	T30	VCC	AB4	VCCA
A3	SKTOCC#	D31	VCC	K5	VCC	T31	VSS	AB5	VSS
A4	Reserved	E1	VSS	K6	VSS	U1	VCC	AB6	D63#
A5	VSS	E2	VCC	K7	VCC	U2	VSS	AB7	PWRGOOD
A6	A32#	E3	VID1	K8	VSS	U3	VCC	AB8	VCC
A7	A33#	E4	BPM5#	K9	VCC	U4	VSS	AB9	DBI3#
A8	VCC	E5	IERR#	K23	VCC	U5	VCC	AB10	D55#
A9	A26#	E6	VCC	K24	VSS	U6	VSS	AB11	VSS
A10	A20#	E7	BPM2#	K25	VCC	U7	VCC	AB12	D51#
A11	VSS	E8	BPM4#	K26	VSS	U8	VSS	AB13	D52#
A12	A14#	E9	VSS	K27	VCC	U9	VCC	AB14	VCC
A13	A10#	E10	AP0#	K28	VSS	U23	VCC	AB15	D37#
A14	VCC	E11	BR2# 1	K29	VCC	U24	VSS	AB16	D32#
A15	Reserved	E12	VCC	K30	VSS	U25	VCC	AB17	D31#
A16	Reserved	E13	A28#	K31	VCC	U26	VSS	AB18	VCC
A17	LOCK#	E14	A24#	L1	VSS	U27	VCC	AB19	D14#
A18	VCC	E15	VSS	L2	VCC	U28	VSS	AB20	D12#
A19	A7#	E16	COMP1	L3	VSS	U29	VCC	AB21	VSS
A20	A4#	E17	VSS	L4	VCC	U30	VSS	AB22	D13#
A21	VSS	E18	DRDY#	L5	VSS	U31	VCC	AB23	D9#
A22	A3#	E19	TRDY#	L6	VCC	V1	VSS	AB24	VCC
A23	HITM#	E20	VCC	L7	VSS	V2	VCC	AB25	D8#
A24	VCC	E21	RS0#	L8	VCC	V3	VSS	AB26	D7#
A25	TMS	E22	HIT#	L9	VSS	V4	VCC	AB27	VSS
A26	Reserved	E23	VSS	L23	VSS	V5	VSS	AB28	SM_EP_A2
A27	VSS	E24	TCK	L24	VCC	V6	VCC	AB29	SM_EP_A1
A28	VCC	E25	TDO	L25	VSS	V7	VSS	AB30	VCC
A29	VSS	E26	VCC	L26	VCC	V8	VCC	AB31	VSS
A30	VCC	E27	FERR#	L27	VSS	V9	VSS	AC1	Reserved
A31	VSS	E28	VCC	L28	VCC	V23	VSS	AC2	VSS
B1	Reserved	E29	VSS	L29	VSS	V24	VCC	AC3	VCC
B2	VSS	E30	VCC	L30	VCC	V25	VSS	AC4	VCC
В3	VID4	E31	VSS	L31	VSS	V26	VCC	AC5	D60#
B4	VCC	F1	VCC	M1	VCC	V27	VSS	AC6	D59#
B5	OTDEN	F2	VSS	M2	VSS	V28	VCC	AC7	VSS
B6	VCC	F3	VID0	МЗ	VCC	V29	VSS	AC8	D56#
B7	A31#	F4	VCC	M4	VSS	V30	VCC	AC9	D47#
B8	A27#	F5	BPM3#	M5	VCC	V31	VSS	AC10	VCC

Pin No	Pin Name	Pin No	Pin Name	Pin No	Pin Name	Pin No	Pin Name	Pin No	Pin Name
B9	VSS	F6	BPM0#	M6	VSS	W1	VCC	AC11	D43#
B10	A21#	F7	VSS	M7	VCC	W2	VSS	AC12	D41#
B11	A22#	F8	BPM1#	M8	VSS	W3	Reserved	AC13	VSS
B12	VCC	F9	GTLREF	M9	VCC	W4	VSS	AC14	D50#
B13	A13#	F10	VCC	M23	VCC	W5	BCLK1	AC15	DP2#
B14	A12#	F11	BINIT#	M24	VSS	W6	TESTHI0	AC16	VCC
B15	VSS	F12	BR1#	M25	VCC	W7	TESTHI1	AC17	D34#
B16	A11#	F13	VSS	M26	VSS	W8	TESTHI2	AC18	DP0#
B17	VSS	F14	ADSTB1#	M27	VCC	W9	GTLREF	AC19	VSS
B18	A5#	F15	A19#	M28	VSS	W23	GTLREF	AC20	D25#
B19	REQ0#	F16	VCC	M29	VCC	W24	VSS	AC21	D26#
B20	VCC	F17	ADSTB0#	M30	VSS	W25	VCC	AC22	VCC
B21	REQ1#	F18	DBSY#	M31	VCC	W26	VSS	AC23	D23#
B22	REQ4#	F19	VSS	N1	VCC	W27	VCC	AC24	D20#
B23	VSS	F20	BNR#	N2	VSS	W28	VSS	AC25	VSS
B24	LINT0	F21	RS2#	N3	VCC	W29	VCC	AC26	D17#
B25	PROCHOT#	F22	VCC	N4	VSS	W30	VSS	AC27	DBI0#
B26	VCC	F23	GTLREF	N5	VCC	W31	VCC	AC28	SM_CLK
B27	VCCSENSE	F24	TRST#	N6	VSS	Y1	VSS	AC29	SM_DAT
B28	VSS	F25	VSS	N7	VCC	Y2	VCC	AC30	VSS
B29	VCC	F26	THERMTRIP #	N8	VSS	Y3	Reserved	AC31	VCC
B30	VSS	F27	A20M#	N9	VCC	Y4	BCLK0	AD1	Reserved
B31	VCC	F28	VSS	N23	VCC	Y5	VSS	AD2	VCC
C1	VSS	F29	VCC	N24	VSS	Y6	TESTHI3	AD3	VSS
C2	VCC	F30	VSS	N25	VCC	Y7	VSS	AD4	VCCIOPLL
C3	VID3	F31	VCC	N26	VSS	Y8	RESET#	AD5	TESTHI5
C4	VCC	G1	VSS	N27	VCC	Y9	D62#	AD6	VCC
C5	Reserved	G2	VCC	N28	VSS	Y10	VCC	AD7	D57#
C6	RSP#	G3	VSS	N29	VCC	Y11	DSTBP3#	AD8	D46#
C7	VSS	G4	VCC	N30	VSS	Y12	DSTBN3#	AD9	VSS
C8	A35#	G5	VSS	N31	VCC	Y13	VSS	AD10	D45#
C9	A34#	G6	VCC	P1	VSS	Y14	DSTBP2#	AD11	D40#
C10	VCC	G7	VSS	P2	VCC	Y15	DSTBN2#	AD12	VCC
C11	A30#	G8	VCC	P3	VSS	Y16	VCC	AD13	D38#
C12	A23#	G9	VSS	P4	VCC	Y17	DSTBP1#	AD14	D39#
C13	VSS	G23	LINT1	P5	VSS	Y18	DSTBN1#	AD15	VSS
C14	A16#	G24	VCC	P6	VCC	Y19	VSS	AD16	COMP0
C15	A15#	G25	VSS	P7	VSS	Y20	DSTBP0#	AD17	VSS
C16	VCC	G26	VCC	P8	VCC	Y21	DSTBN0#	AD18	D36#
C17	A8#	G27	VSS	P9	VSS	Y22	VCC	AD19	D30#
C18	A6#	G28	VCC	P23	VSS	Y23	D5#	AD20	VCC
C19	VSS	G29	VSS	P24	VCC	Y24	D2#	AD21	D29#
C20	REQ3#	G30	VCC	P25	VSS	Y25	VSS	AD22	DBI1#
C21	REQ2#	G31	VSS	P26	VCC	Y26	D0#	AD23	VSS
C22	VCC	H1	VCC	P27	VSS	Y27	Reserved	AD24	D21#

Pin No	Pin Name	Pin No	Pin Name						
C23	DEFER#	H2	VSS	P28	VCC	Y28	Reserved	AD25	D18#
C24	TDI	НЗ	VCC	P29	VSS	Y29	SM_TS1_A1	AD26	VCC
C25	VSS	H4	VSS	P30	VCC	Y30	VCC	AD27	D4#
C26	IGNNE#	H5	VCC	P31	VSS	Y31	VSS	AD28	SM_ALERT#
C27	SMI#	H6	VSS	R1	VCC	AA1	VCC	AD29	SM_WP
C28	VCC	H7	VCC	R2	VSS	AA2	VSS	AD30	VCC
C29	VSS	H8	VSS	R3	VCC	AA3	BSEL0 2	AD31	VSS
C30	VCC	H9	VCC	R4	VSS	AA4	VCC	AE2	VSS
C31	VSS	H23	VCC	R5	VCC	AA5	VSSA	AE3	VCC
D1	VCC	H24	VSS	R6	VSS	AA6	VCC	AE4	Reserved
D2	VSS	H25	VCC	R7	VCC	AA7	TESTHI4	AE5	TESTHI6
D3	VID2	H26	VSS	R8	VSS	AA8	D61#	AE6	SLP#
D4	STPCLK#	H27	VCC	R9	VCC	AA9	VSS	AE7	D58#
D5	VSS	H28	VSS	R23	VCC	AA10	D54#	AE8	VCC
D6	INIT#	H29	VCC	R24	VSS	AA11	D53#	AE9	D44#
D7	MCERR#	H30	VSS	R25	VCC	AA12	VCC	AE10	D42#
D8	VCC	H31	VCC	R26	VSS	AA13	D48#	AE11	VSS
D9	AP1#	J1	VSS	R27	VCC	AA14	D49#	AE12	DBI2#
D10	BR3# 1	J2	VCC	R28	VSS	AA15	VSS	AE13	D35#
D11	VSS	J3	VSS	R29	VCC	AA16	D33#	AE14	VCC
D12	A29#	J4	VCC	R30	VSS	AA17	VSS	AE15	Reserved
D13	A25#	J5	VSS	R31	VCC	AA1	D24#	AE16	Reserved
D14	VCC	J6	VCC	T1	VSS	AA19	D15#	AE17	DP3#
D15	A18#	J7	VSS	T2	VCC	AA20	VCC	AE18	VCC
D16	A17#	J8	VCC	Т3	VSS	AA21	D11#	AE19	DP1#
D17	A9#	J9	VSS	T4	VCC	AA22	D10#	AE20	D28#
D18	VCC	J23	VSS	T5	VSS	AA23	VSS	AE21	VSS
D19	ADS#	J24	VCC	T6	VCC	AA24	D6#	AE22	D27#
D20	BR0#	J25	VSS	T7	VSS	AA25	D3#	AE23	D22#
D21	VSS	J26	VCC	T8	VCC	AA26	VCC	AE24	VCC
D22	RS1#	J27	VSS	Т9	VSS	AA27	D1#	AE25	D19#
D23	BPRI#	J28	VCC	T23	VSS	AA28	SM_TS1_A0	AE26	D16#
D24	VCC	J29	VSS	T24	VCC	AA29	SM_EP_A0	AE27	VSS
D25	Reserved	J30	VCC	T25	VSS	AA30	VSS	AE28	SM_VCC
D26	VSSSENSE	J31	VSS	T26	VCC	AA31	VCC	AE29	SM_VCC
D27	VSS	K1	VCC	T27	VSS	AB1	VSS	AE30	Inert 3
D28	VSS	K2	VSS	T28	VCC	AB2	VCC		
Mataa		*			•	*	•		

Notes:

- 1. These are "Reserved " pins on the Intel[®] Xeon™ processor. In systems utilizing the Intel[®] Xeon™ processor, the system designer must terminate these signals to the processor VCC.
- 2. Baseboards treating AA3 and AB3 as Reserved will operate correctly with a bus clock of 100 MHz.
- 3. The FC-mPGA2P package contains an extra pin (located at location AE30) compared to the INT-mPGA package. This additional pin serves as a keying mechanism to prevent the FC-mPGA2P package from being installed in the 603-pin socket. Since the additional contact for pin AE30 is electrically inert, the 604-pin socket will not have a solder ball at this location.

8.4 I²C Header

Table 25. SCSI HDD Header Pin-out (J3K2, J4K1)

Pin	Signal Name	Description
1	3VSB SDA	Data Line
2	GND	
3	3VSB SCL	Clock Line
4	+5VSB	Power Line

8.5 PCI Slot Connector

There are three PCI buses implemented on the baseboard. PCI segment A supports 5V 32-bit/33MHz PCI, segment B supports 3.3V 64-bit/100MHz PCI-X, and segment C supports 3.3V 64-bit/66MHz PCI operation. All segments support full-length PCI add-in cards. The pin-out for each segment is below.

Table 26. P32-A 5V 32-bit/33-MHz PCI Slot Pin-out (J4B1, J3B1)

Pin	Side B	Side A	Pin	Side B	Side A
1	-12V	TRST#	32	AD[17]	AD[16]
2	TCK	+12V	33	C/BE[2]#	+3.3V
3	Ground	TMS	34	Ground	FRAME#
4	TDO	TDI	35	IRDY#	Ground
5	+5V	+5V	36	+3.3V	TRDY#
6	+5V	INTA#	37	DEVSEL#	Ground
7	INTB#	INTC#	38	Ground	STOP#
8	INTD#	+5V	39	LOCK#	+3.3V
9	PRSNT1#	Reserved	40	PERR#	SMBCLK
10	Reserved	+5V (I/O)	41	+3.3V	SMBDAT
11	PRSNT2#	Reserved	42	SERR#	Ground
12	Ground	Ground	43	+3.3V	PAR
13	Ground	Ground	44	C/BE[1]#	AD[15]
14	Reserved	3.3Vaux	45	AD[14]	+3.3V
15	Ground	RST#	46	Ground	AD[13]
16	CLK	+5V (I/O)	47	AD[12]	AD[11]
17	Ground	GNT#	48	AD[10]	Ground
18	REQ#	Ground	49	Ground	AD[09]
19	+5V (I/O)	PME#	50	CONNECTOR KEY	′
20	D[31]	AD[30]	51	CONNECTOR KEY	′
21	AD[29]	+3.3V	52	AD[08]	C/BE[0]#
22	Ground	AD[28]	53	AD[07]	+3.3V
23	AD[27]	AD[26]	54	+3.3V	AD[06]
24	AD[25]	Ground	55	AD[05]	AD[04]
25	+3.3V	AD[24]	56	AD[03]	Ground
26	C/BE[3]#	IDSEL	57	Ground	AD[02]
27	AD[23]	+3.3V	58	AD[01]	AD[00]
28	Ground	AD[22]	59	+5V (I/O)	+5V (I/O)
29	AD[21]	AD[20]	60	ACK64#	REQ64#
30	AD[19]	Ground	61	+5V	+5V
31	+3.3V	AD[18]	62	+5V	+5V

Table 27. P64-B 3.3V 64-bit/100-MHz PCI-X Slot Pin-out (J2B1, J2B2)

Pin	Side B	Side A	Pin	Side B	Side A
1	-12V	TRST#	49	M66EN	AD[09]
2	TCK	+12V	50	Ground	Ground
3	Ground	TMS	51	Ground	Ground
4	TDO	TDI	52	AD[08]	C/BE[0]#
5	+5V	+5V	53	AD[07]	+3.3V
6	+5V	INTA#	54	+3.3V	AD[06]
7	INTB#	INTC#	55	AD[05]	AD[04]
8	INTD#	+5V	56	AD[03]	Ground
9	PRSNT1#	Reserved	57	Ground	AD[02]
10	Reserved	+3.3V (I/O)	58	AD[01]	AD[00]
11	PRSNT2#	Reserved	59	+3.3V (I/O)	+3.3V (I/O)
12	CONNECTOR	RKEY	60	ACK64#	REQ64#
13	CONNECTOR	R KEY	61	+5V	+5V
14	Reserved	3.3Vaux	62	+5V	+5V
15	Ground	RST#		CONNECTOR R	(EY
16	CLK	+3.3V (I/O)		CONNECTOR R	(EY
17	Ground	GNT#	63	Reserved	Ground
18	REQ#	Ground	64	Ground	C/BE[7]#
19	+3.3V (I/O)	PME#	65	C/BE[6]#	C/BE[5]#
20	AD[31]	AD[30] A	66	C/BE[4]#	+3.3V (I/O)
21	AD[29]	+3.3V	67	Ground	PAR64
22	Ground	AD[28]	68	AD[63]	AD[62]
23	AD[27]	AD[26]	69	AD[61]	Ground
24	AD[25]	Ground	70	+3.3V (I/O)	AD[60]
25	+3.3V	AD[24]	71	AD[59]	AD[58]
26	C/BE[3]#	IDSEL	72	AD[57]	Ground
27	AD[23]	+3.3V	73	Ground	AD[56]
28	Ground	AD[22]	74	AD[55]	AD[54]
29	AD[21]	AD[20]	75	AD[53]	+3.3V (I/O)
30	AD[19]	Ground	76	Ground	AD[52]
31	+3.3V	AD[18]	77	AD[51]	AD[50]
32	AD[17]	AD[16]	78	AD[49]	Ground
33	C/BE[2]#	+3.3V	79	+3.3V (I/O)	AD[48]
34	Ground	FRAME#	80	AD[47]	AD[46]
35	IRDY#	Ground	81	AD[45]	Ground
36	+3.3V	TRDY#	82	Ground	AD[44]
37	DEVSEL#	Ground	83	AD[43]	AD[42]
38	PCIXCAP	STOP#	84	AD[41]	+3.3V (I/O)
39	LOCK#	+3.3V	85	Ground	AD[40]
40	PERR#	SMBCLK	86	AD[39]	AD[38]
41	+3.3V	SMBDAT	87	AD[37]	Ground
42	SERR#	Ground	88	+3.3V (I/O)	AD[36]
43	+3.3V	PAR	89	AD[35]	AD[34]

44	C/BE[1]#	AD[15]	90	AD[33]	Ground
45	AD[14]	+3.3V	91	Ground	AD[32]
46	Ground	AD[13]	92	Reserved	Reserved
47	AD[12]	AD[11]	93	Reserved	Ground
48	AD[10]	Ground	94	Ground	Reserved

Table 28. P64-C 3.3V 64-bit/66-MHz PCI Slot Pin-out (J1B1)

Pin	Side B	Side A	Pin	Side B	Side A
1	-12V	TRST#	49	M66EN	AD[09]
2	TCK	+12V	50	Ground	Ground
3	Ground	TMS	51	Ground	Ground
4	TDO	TDI	52	AD[08]	C/BE[0]#
5	+5V	+5V	53	AD[07]	+3.3V
6	+5V	INTA#	54	+3.3V	AD[06]
7	INTB#	INTC#	55	AD[05]	AD[04]
8	INTD#	+5V	56	AD[03]	Ground
9	PRSNT1#	Reserved	57	Ground	AD[02]
10	Reserved	+3.3V (I/O)	58	AD[01]	AD[00]
11	PRSNT2#	Reserved	59	+3.3V (I/O)	+3.3V (I/O)
12	CONNECTOR	RKEY	60	ACK64#	REQ64#
13	CONNECTOR	RKEY	61	+5V	+5V
14	Reserved	3.3Vaux	62	+5V	+5V
15	Ground	RST#		CONNECTOR I	KEY
16	CLK	+3.3V (I/O)		CONNECTOR I	KEY
17	Ground	GNT#	63	Reserved	Ground
18	REQ#	Ground	64	Ground	C/BE[7]#
19	+3.3V (I/O)	PME#	65	C/BE[6]#	C/BE[5]#
20	AD[31]	AD[30] A	66	C/BE[4]#	+3.3V (I/O)
21	AD[29]	+3.3V	67	Ground	PAR64
22	Ground	AD[28]	68	AD[63]	AD[62]
23	AD[27]	AD[26]	69	AD[61]	Ground
24	AD[25]	Ground	70	+3.3V (I/O)	AD[60]
25	+3.3V	AD[24]	71	AD[59]	AD[58]
26	C/BE[3]#	IDSEL	72	AD[57]	Ground
27	AD[23]	+3.3V	73	Ground	AD[56]
28	Ground	AD[22]	74	AD[55]	AD[54]
29	AD[21]	AD[20]	75	AD[53]	+3.3V (I/O)
30	AD[19]	Ground	76	Ground	AD[52]
31	+3.3V	AD[18]	77	AD[51]	AD[50]
32	AD[17]	AD[16]	78	AD[49]	Ground
33	C/BE[2]#	+3.3V	79	+3.3V (I/O)	AD[48]
34	Ground	FRAME#	80	AD[47]	AD[46]
35	IRDY#	Ground	81	AD[45]	Ground
36	+3.3V	TRDY#	82	Ground	AD[44]
37	DEVSEL#	Ground	83	AD[43]	AD[42]
38	Ground	STOP#	84	AD[41]	+3.3V (I/O)

Pin	Side B	Side A	Pin	Side B	Side A
39	LOCK#	+3.3V	85	Ground	AD[40]
40	PERR#	Reserved*	86	AD[39]	AD[38]
41	+3.3V	Reserved*	87	AD[37]	Ground
42	SERR#	Ground	88	+3.3V (I/O)	AD[36]
43	+3.3V	PAR	89	AD[35]	AD[34]
44	C/BE[1]#	AD[15]	90	AD[33]	Ground
45	AD[14]	+3.3V	91	Ground	AD[32]
46	Ground	AD[13]	92	Reserved	Reserved
47	AD[12]	AD[11]	93	Reserved	Ground
48	AD[10]	Ground	94	Ground	Reserved

8.6 AGP 3.0 Pro50 Connector

The AGP 3.0 Pro connector is designed as an extension to the existing AGP connectors. The standard AGP connector is extended on each end to build the AGP Pro connector. Below is the pin-out of the AGP connector on the baseboard.

Pin# В Α Pin# В Pin# В Α GND OVRCNT# 12V 23 GND 45 KEY KEY 2 3.3VAUX 46 **DEVSEL** 5.0V TYPEDET# 2 24 Reserved 1 **TRDY** 3 5.0V 25 VCC3.3 VCC3.3 47 Vddq1.5 STOP GC DFT#2 4 USB+ USB-26 AD31 AD30 48 PERR PME# AD28 49 GND 5 **GND** GND 27 AD29 GND VCC3.3 6 INTB# INTA# 28 VCC3.3 50 SERR PAR CLK RST# 29 AD27 AD26 51 C#/BE1 AD15 REQ GNT 30 AD25 AD24 52 Vddq1.5 Vddq1.5 8 VCC3.3 VCC3.3 31 GND GND 53 AD14 AD13 9 10 ST0 ST1 32 AD STBF1 AD STBS1 54 AD12 AD11 11 ST2 MB DET# 33 AD23 C#/BF3 55 GND GND 12 **RBF** DBI HI 34 Vddq1.5 Vddq1.5 56 AD10 AD9 AD21 AD22 57 AD8 C#/BE0 13 GND GND 35 14 WBF Vddq1.5 DBI LO 36 AD19 AD20 58 Vdda1.5 SBA0# 37 AD STBF0 AD STBS0 15 SBA1# GND GND 59 16 VCC3.3 VCC3.3 38 AD17 AD18 60 AD7 AD6 SBA2# SBA3# C#/BE2 AD16 GND GND 17 39 61 SB STBF SB STBS 40 Vddq1.5 Vddq1.5 62 AD5 AD4 18 19 GND GND 41 IRDY FRAME 63 AD3 AD2 20 SBA4# SBA5# 42 KEY KEY 64 Vdda1.5 Vdda1.5 SBA6# SBA7# 21 43 **KEY KEY** 65 AD1 AD0 KEY 66 22 44 KEY AGPVrefcg **AGPVrefgc** Reserved 1 Reserved 1

Table 29. AGP 3.0 Pro Connector Pin-out (J4C1)

Notes:

- 1. Reserved pins are only for future use by the AGP3.0 interface specification.
- 2. TYPEDET# and GC_DET# should be both grounded by AGP3.0 and Universal AGP3.0 cards. These will be pulled up to the appropriate voltage by the motherboard.
- 3. IDSEL# is not a pin on the AGP3.0 connector. AGP3.0 graphics components should connect the AD16 signal to the IDSEL# function internal to the component.

8.7 Front Panel Connector

A standard SSI 34-pin header is provided to support a system front panel. The header contains reset, NMI, power control buttons, and LED indicators. The following table details the pin-out of this header.

Table 30. Front Panel 34-Pin Header Pin-out (J1J1)

Signal Name	Pin	Pin	Signal Name
ACPI_LEDgrn	1	2	SB5V
KEY	3	4	*FAN_FAULT LED
ACPI_LEDamber	5	6	*FAN_FAULT LED#
HDD_LED	7	8	*SYS_FAULT LED
HDD_LED#	9	10	*SYS_FAULT LED#
ACPI switch	11	12	NIC2 ACT_LED
ACPI switch (GND)	13	14	NIC2 ACT_LED#
RESET switch	15	16	SMB SDA
RESET switch (GND)	17	18	SMB SCL
*Sleep switch	19	20	*INDRUDER
*Sleep switch (GND)	21	22	NIC1 ACT_LED
NMI switch#	23	24	NIC1 ACT_LED#
Key	25	26	Key
NC	27	28	NC
NC	29	30	NC
NC	31	32	NC
NC	33	34	NC

Note:

8.8 VGA Connector

The following table details the pin-out of the VGA connector.

Table 31. VGA Connector Pin-out (J7A1)

Signal Name	Pin	Pin	Signal Name
RED	1	9	Fused VCC (+5V)
GREEN	2	10	NC
BLUE	3	11	NC
NC	4	12	DDCDAT
GND	5	13	HSY
GND	6	14	VSY
GND	7	15	DDCCLK
GND	8	16	NC
		17	NC

Note:

NC (No Connect) in this project

^{* =&}gt; NC (No Connect) in this project

8.9 NIC Connector

The server board SE7505VB2 supports two NIC RJ45 connectors. The following table details the pin-out of the connector.

Signal Name Pin Pin Signal Name GND NIC GIGA MDI 0N 10 NIC_GIGA_MDI 0P NIC GIGA MDI 2N 2 11 NIC GIGA MDI 2P 3 12 GND NIC GIGA MDI 1P NIC GIGA LINKUP L 4 13 NIC GIGA MDI 1N 5 14 NIC GIGA ACT L NIC_GIGA_LINK1000 L GND 6 15 GND 16 NIC GIGA LINK100 L 7 NIC_GIGA_MDI_3P 17 GND 8 NIC GIGA MDI 3N 9 18 GND

Table 32. NIC1 (10/100) Connector Pin-out (J5A1)

Table 33. NIC2 (Gbit 10/100/1000) Connector Pin-out (J6A1)

Signal Name	Pin	Pin	Signal Name
NIC_TXUP	1	8	GND
GND	2	9	P3V_STAY
NIC_TXUN	3	10	NIC_100_L
NIC_RXIP	4	11	NIC_ACT_L
GND	5	12	LK_STATUS2_L
NIC_RXIN	6	13	GND
NC	7	14	GND

8.10 IDE Connector

The board provides two 40-pin ATA-100 IDE connectors

Table 34. ATA 40-pin Connector Pin-out (J3K2, J4K1)

Pin	Signal Name	Pin	Signal Name
1	RESET#	2	GND
3	IDE_DD7	4	IDE_DD8
5	IDE_DD6	6	IDE_DD9
7	IDE_DD5	8	IDE_DD10
9	IDE_DD4	10	IDE_DD11
11	IDE_DD3	12	IDE_DD12
13	IDE_DD2	14	IDE_DD13
15	IDE_DD1	16	IDE_DD14
17	IDE_DD0	18	IDE_DD15
19	GND	20	KEY
21	IDE_DMAREQ	22	GND

Pin	Signal Name	Pin	Signal Name
23	IDE_IOW#	24	GND
25	IDE_IOR#	26	GND
27	IDE_IORDY	28	GND
29	IDE_DMAACK#	30	GND
31	IRQ_IDE	32	Test Point
33	IDE_A1	34	DIAG
35	IDE_A0	36	IDE_A2
37	IDE_DCS0#	38	IDE_DCS1#
39	IDE_HD_ACT#	40	GND

8.11 SATA Connector

Integrated on the baseboard is the Silicon Image 3112A dual port serial ATA controller with two serial ATA connectors. The pin-out for these two connectors is listed below.

Table 35. SATA Connector Pin-out (J1H1)

Pin	Signal Name
1	GND
2	S_TXP2N
3	S_TXN2N
4	GND
5	S_RXN2N
6	S_RXP2N
7	GND
8	GND
9	GND

Table 36. SATA Connector Pin-out (J1H2)

Pin	Signal Name
1	GND
2	S_TXP1N
3	S_TXN1N
4	GND
5	S_RXN1N
6	S_RXP1N
7	GND
8	GND
9	GND

8.12 USB Connector

The following table provides the pin-out for the three external USB connectors.

Table 37. USB Connectors Pin-out (J9A2)

Pin	Signal Name
1	Fused VCC (+5V /w over current monitor of both port 0 and 1)
2	DATAL0 (Differential data line paired with DATAH0)
3	DATAH0 (Differential data line paired with DATAL0)
4	GND
5	Fused VCC (+5V /w over current monitor of both port 0 and 1)
6	DATAL1 (Differential data line paired with DATAH1)
7	DATAH1 (Differential data line paired with DATAL1)
8	GND
9	Fused VCC (+5V /w over current monitor of both port 0 and 1)
10	DATAL2 (Differential data line paired with DATAH2)
11	DATAH2 (Differential data line paired with DATAL2)
12	GND
13	GND
14	GND
15	GND
16	GND

A header on the server board provides an option to support one additional USB connector. The pin-out of the header is detailed in the following table.

Table 38. Optional USB Connection Header Pin-out (J5K1)

Signal Name	Pin	Pin	Signal Name
NC	1	2	USB2_VBUS2
NC	3	4	USB_ICH4_P3N_CONN_IND
NC	5	6	USB_ICH4_P3P_CONN_IND
NC	7	8	GND
Key	9	10	NC

8.13 Floppy Connector

The board provides a standard 34-pin interface to the floppy drive controller. The following tables detail the pin-out of the 34-pin floppy connector.

Pin Pin Signal Name Signal Name GND **FDDENSEL** 2 3 Unused GND 4 KEY 5 FDDRATE0 6 GND 7 8 FDINDEX# **GND** 9 10 FDMTR0# GND 11 12 FDR1# GND FDR0# 13 14 GND 15 16 FDMTR1# Unused 17 18 **FDDIR** GND 19 20 FDSTEP# GND 21 FDWDATA# 22 GND 23 24 FDWGATE# FDTRK0# **GND** 25 26 Unused 27 28 FLWP# GND 29 30 FRDATA# GND 31 32 FHDSEL# GND 33 FDSKCHG# 34

Table 39. Legacy 34-pin Floppy Connector Pin-out (J3K1)

8.14 Serial Port Connector

Two serial ports are provided on the Server Board SE7505VB2.

- A standard, external DB9 serial connector is located on the back edge of the baseboard to supply a Serial A interface
- A Serial B port is provided through a 9-pin header on the server board.

The following tables detail the pin-outs of these two ports.

Table 40. External DB9 Serial A Port Pin-out (J8A1)

Signal Name	Pin	Pin	Signal Name
SERIAL_DCD1_FB	1	6	SERIAL_DSR1_FB
SERIAL_RX1_FB	2	7	SERIAL_RTS1_FB
SERIAL_TX1_FB	3	8	SERIAL_CTS1_FB
SERIAL_DTR1_FB	4	9	SERIAL_RING1_FB
GND	5	10	GND
		11	GND

Signal Name Pin Pin Signal Name SERIAL DCD2 FB SERIAL DSR2 FB 2 SERIAL RX2 FB 3 4 SERIAL RTS2 FB SERIAL TX2 FB 5 6 SERIAL CTS2 FB SERIAL_DTR2_FB SERIAL RING2 FB 7 8

10

Key

9

Table 41. 9-pin Header Serial B Port Pin-out (J1J2)

8.15 Keyboard and Mouse Connector

GND

Two PS/2 ports are provided for use by a keyboard and a mouse. The following table details the pin-out of the PS/2 connectors.

Signal Name **PS/2 Connectors** Pin PS2 KBDATA FB Keyboard TP_PS2 2 2 GND 3 PS2 KMPWR FB 4 PS2 FBCLK FB 5 TP PS2 6 6 Mouse 7 PS2 MSEDATA FB TP PS2 8 8 9 GND 10 PS2 KMPWR RT 11 PS2 PSECLK FB 12 TP FS2 12 13,14,15,16,17 GND

Table 42. Keyboard and Mouse PS/2 Connectors Pin-out (J9A1)

8.16 Miscellaneous Headers

8.16.1 Fan Header

There are six 3-pin fan headers. All fans provide speed monitoring. The fan headers are labeled, CPU Fan 1 and 2, and SysFan 1 - 4. All fan headers have the same pin-out and are detailed below.

Table 43. Three-pin Fan Headers Pin-out (J8A3, J7B1, J5K2, J5K3, J8A2, J5A2)

Pin	Signal Name	Type	Description
1	Ground	Power	GROUND is the power supply ground
2	Fan Power	Power	Fan Power
3	Fan Tach	Out	FAN_TACH signal is connected to the sIO to monitor the FAN speed.

8.16.2 Intrusion Cable Connector

Table 44. Intrusion Cable Connector Pin-Out

Pin	Signal Name		
1	Intruder_FET_L		
2	P3V_STBY		

9. Configuration Jumpers

This section describes configuration jumper options on the Intel Server Board SE7505VB2.

9.1 System Recovery and Update Jumpers

A 10-pin block (J4J1), located just below the DIMM connectors, provides a total of four 2-pin jumper blocks that are used to configure several system recovery and update options. The figure below shows the jumper pins and their functions. The factory defaults are set to a protected mode for each function.

Two jumpers are stored on four pins during normal operation. The BIOS bootblock write protect jumper on pins 7-8 should be left on these pins at all times except when instructed by the BIOS release notes to remove it. The jumper stored on pins 9-10 is used to perform different functions depending on the pins it is placed. For normal operation, this jumper should be on the storage pins.



Figure 10. System Recovery and Update Jumpers (J4J1)

The following table describes each jumper option.

Table 45. System Recovery and Update Jumper Options

Function	Pin – Pin	Off	On	
		(open=1)	(close=0)	
Clear Password	1 – 2 (J4J1 pin 1-2)	Disable	Enable	These four pins are connected to GPIs
Recovery Mode	3 – 4 (J4J1 pin 3-4)	Disable		of SIO. The system BIOS reads these GPIs status and decides whether or not
Clear CMOS	5 – 6 (J4J1 Pin 5-6)	Disable	I	to execute related task. The clear
BIOS boot block protect	7 – 8 (J4J1 pin 7-8)	Disable		CMOS status is reflected to ICH4.
Storage location	9 – 10 (J4J1 pin 9-10)	N/A	N/A	Defaults are in bold.

10. BIOS

10.1 Using the BIOS Setup Utility

This section describes the BIOS Setup Utility options. For more details on the BIOS and its functionality, contact your Intel field representative to obtain the *Intel Server Board SE7505VB2 BIOS External Product Specification* (Note that access to this document is restricted). Use BIOS Setup to change the server configuration defaults. You can run BIOS Setup with or without an operating system being present.

10.1.1 If You Cannot Access Setup

If you are not able to access BIOS Setup, you might need to clear the CMOS memory.

10.1.2 Starting Setup

You can enter and start BIOS Setup under several conditions:

- When you turn on the server, after POST completes the memory test
- When you have moved the CMOS jumper on the server board to the "Clear CMOS" position (enabled)

In the two conditions listed above, after rebooting, you will see this prompt:

```
Press <F2> to enter SETUP
```

In a third condition, when CMOS/NVRAM has been corrupted, you will see other prompts but not the <F2> prompt:

```
Warning: CMOS checksum invalid
Warning: CMOS time and date not set
```

When this happens, the BIOS will load default values for CMOS and attempt to boot.

10.1.3 Setup Menus

Each BIOS Setup menu page contains a number of features. Except for those that are provided for informational purposes, each feature is associated with a value field that contains user-selectable parameters. Parameters may be changed depending upon the security option chosen. If a value is not changeable due to insufficient security privileges (or other reasons), the feature's value field becomes inaccessible.

The bottom portion of the BIOS Setup screen provides a list of commands that are used for navigating the Setup utility. Table 46 describes the keyboard commands you can use in the BIOS Setup menus.

Table 46. Keyboard Commands

Press	Description			
<f1></f1>	Help - Pressing F1 on any menu invokes the general Help window.			
$\leftarrow \rightarrow$	The left and right arrow keys are used to move between the major menu pages. The keys have no affect if a submenu or pick list is displayed.			
↑	Select Item up - The up arrow is used to select the previous value in a menu item's option list, or a value field pick list. Pressing the Enter key activates the selected item.			
\	Select Item down - The down arrow is used to select the next value in a menu item's option list, or a value field pick list. Pressing the Enter key activates the selected item.			
F5/-	Change Value - The minus key or the F5 function key is used to change the value of the current item to the previous value. This key scrolls through the values in the associated pick list without displaying the full list.			
F6/+	Change Value - The plus key or the F6 function key is used to change the value of the current menu item to the next value. This key scrolls through the values in the associated pick list without displaying the full list. On 106-key Japanese keyboards, the plus key has a different scan code than the plus key on the other keyboard, but it has the same effect.			
<enter></enter>	Execute Command - The Enter key is used to activate submenus when the selected feature is a submenu, or to display a pick list if a selected feature has a value field, or to select a sub-field for multivalued features like time and date. If a pick list is displayed, the Enter key will undo the pick list, and allow another selection in the parent menu.			
<esc></esc>	Exit - The ESC key provides a mechanism for backing out of any field. This key will undo the pressing of the Enter key. When the ESC key is pressed while editing any field or selecting features of a menu, the parent menu is re-entered. When the ESC key is pressed in any submenu, the parent menu is re-entered. When the ESC key is pressed in any major menu, the exit confirmation window is displayed and the user is asked whether changes can be discarded.			
<f9></f9>	Setup Defaults - Pressing F9 causes the following to appear:			
	Setup Confirmation			
	Load default configuration now?			
	[Yes] [No]			
	If "Yes" is selected and the Enter key is pressed, all Setup fields are set to their default values. If "No" is selected and the Enter key is pressed, or if the ESC key is pressed, the user is returned to where they were before F9 was pressed without affecting any existing field values.			
<f10></f10>	Save and Exit - Pressing F10 causes the following message to appear:			
	Setup Confirmation			
	Save Configuration changes and exit now?			
	[<u>Yes</u>] [NO]			
	If "Yes" is selected and the Enter key is pressed, all changes are saved and Setup is exited. If "No" selected and the Enter key is pressed, or the ESC key is pressed, the user is returned to where they were before F10 was pressed without affecting any existing values.			

Table 47 describes the on-screen options you will see in BIOS Setup and what they mean.

Table 47. On-Screen Options

When you see this:	What it means:
On screen, an option is shown but you cannot select it or move to that field.	You cannot change or configure the option in that menu screen. Either the option is auto-configured or auto-detected, or you must use a different Setup screen.
On screen, the phrase <i>Press Enter</i> appears next to the option.	Press <enter> to display a submenu that is either a separate full screen menu or a popup menu with one or more choices.</enter>

The following sections describe the menus and options available in BIOS Setup. Default settings are indicated in bold.

10.1.4 Menu Selection Bar

The Menu Selection Bar is located at the top of the screen and displays the major menu selections available to the user. The menu bar is shown below.

Main	Advanced	Security	Power	Boot	System	Exit	
------	----------	----------	-------	------	--------	------	--

Table 48 lists the menus available in BIOS Setup.

Table 48. Menu Selection Bar

Main	Advanced	Security	Power	Boot	System	Exit
Allocates resources for hardware components	Configures advanced features available through the chipset	Configures passwords and diskette access	Determines what should happen if power is lost and how the power button operates	Specifies device from which the system boots	Provides information about vendor, processor, memory, peripherals	Saves or discards changes to Setup program options

10.1.5 Main Menu

To access this menu, select Main on the menu bar at the top of the screen.

Main	Advanced	Security	Boot	System	Exit
Primary Master					
Primary Slave					
Secondary Master					
Secondary Slave					

Table 49 lists the options available on the Main menu. This menu allocates resources for hardware components.

Table 49. Main Menu

Feature	Choices	Description
System Time	HH:MM:SS	Sets the system time (hour, minutes, and seconds, on a 24-hour clock).
System Date	MM/DD/YYYY	Sets the system date (month, day, year).
Legacy Diskette A	 Disabled 	Selects the diskette type.
	• 1.44 MB, 3 ½" (default)	
Primary Master	Select to display submenu	Displays IDE device selection.
Primary Slave	Select to display submenu	Displays IDE device selection.
Secondary Master	Select to display submenu	Displays IDE device selection.
Secondary Slave	Select to display submenu	Displays IDE device selection.

10.1.5.1 Primary/Secondary, Master/Slave Submenus

To access this submenu, select Main on the menu bar at the top of the screen and then the master or slave to be configured.

Main	Advanced	Security	Power	Boot	System	Exit	
Primary Master							
Primary Slave							
Secondary Master							
Secondary Slave							

There are four IDE submenus: primary master, primary slave, secondary master, and secondary slave. Table 50 shows the format of the IDE submenus. For brevity, only one example is shown.

Table 50. Primary/Secondary, Master/Slave Submenu

Feature	Choices	Description
Туре	No options	Automatically detects the type of IDE device installed.
Multi-Sector Transfers	No options	Specifies the number of sectors that are transferred per block during multiple sector transfers. This option is disabled by default.
LBA Mode Control	No options	Enables Large Block Addressing (LBA) instead of cylinder, head, sector addressing. This option is disabled by default.
32 Bit I/O	Disabled (default)	Enables 32-bit IDE data transfers.
	 Enabled 	
Transfer Mode	No options	Selects the method of moving data to and from the hard drive. Automatically set to <i>Standard</i> , which selects the optimum transfer mode.
Ultra DMA Mode	No options	Enables Ultra DMA mode.

10.1.6 Advanced Menu

To access this menu, select Advanced on the menu bar at the top of the screen.

Main	Advanced	Security	Power	Boot	System	Exit
I	I/O Device Configuration					
(On Board Devices					
F	PCI Configuration					
3	Server Menu					
(Console Redirection					
- E	Event Loggino	3				
I	Hardware Mo	nitor				

Table 51 lists the selections available on the Advanced menu. This menu configures advanced features available through the chipset.

Table 51. Advanced Menu

Feature	Choices	Description		
I/O Device Configuration	Select to display submenu	Configures the I/O ports.		
Onboard Devices	Select to display submenu	Configures the onboard RAID, network, and USB controllers.		
PCI Configuration	Select to display submenu	Configures PCI or RAID devices.		
Server Menu	Select to display submenu	Sets options for server features.		
Console Redirection	Select to display submenu	Provides additional options to configure the console.		
Event Logging	Select to display submenu	Displays the event logs.		
Hardware Monitor	Select to display submenu	Displays voltages, temperatures, and fan speeds for the system.		
Installed O/S	Other Win2000/.NET/ XP (default) NT4 NetWare	Specifies the primary operating system. An incorrect setting can cause some operating systems to behave erratically. Note: If you select NT4, an additional submenu item, NT4 Installation Workaround, will appear. It is disabled by default. To install Windows NT [†] 4.0, you need to change the NT4 Installation Workaround option to <i>Enabled</i> . Disable it to install pertinent service packs.		
Boot-time Diagnostic Screen	• Disabled (default) • Enabled	Enables or disables the boot-time diagnostic screen. Disabled will display the splash screen over the diagnostic screen. This splash screen can be changed to show an OEM-based logo.		

Feature	Choices	Description
Reset Configuration Data	No (default) Yes	Specifies if the extended server configuration data will be reset during the next boot.
		Yes clears the extended server configuration data during the next boot. The system automatically resets this field to No during the next boot.
Large Disk Access Mode	Other DOS (default)	UNIX [†] , NetWare [†] , and other operating systems require this option be set to <i>Other</i> . If you install an operating system and the hard drive fails to install, change this setting and try again. Different operating systems require different representations of drive geometries.
PS/2 Mouse	Disabled	Configures the PS/2 mouse.
	Enabled Auto Detect	Disabled prevents any installed PS/2 mouse from functioning but frees up IRQ 12.
	(default)	Enabled forces the PS/2 mouse port to be enabled even if a mouse is not present.
		Auto Detect will enable the PS/2 mouse only if one is present.
Summary Screen	Disabled	Enables or disables the boot-time hardware/BIOS summary screen.
	Enabled (default)	
Legacy USB Support	Disabled	Enables support for legacy USB. It may be necessary to set this
	Enabled (default)	option to <i>Disable</i> to install NetWare 6.0 SP1.
Hyper-Threading	Disabled Enabled (default)	Allows Intel Xeon processors to run in hyperthreading mode. Enabling this setting will improve throughput significantly on certain applications.

10.1.6.1 I/O Device Configuration Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then I/O Device Configuration.

Main	Advanced	Security	Power	Boot	System	Exit	
	I/O Device C	onfiguration	n				
	On Board De	On Board Device					
	PCI Configur	PCI Configuration					
	Server Menu						
	Console Redirection						
	Event Logging						
	Hardware Mo	onitor					

Table 52 lists the options available through the I/O Device Configuration submenu. This submenu configures the I/O ports on the board.

Table 52. I/O Device Configuration Submenu

Feature	Choices	Description
Serial port A	Disabled	Enables or disables serial port A.
	Enabled (default)	Two devices cannot share the same IRQ. Choosing <i>Disabled</i> makes serial port A unusable.
Base I/O Address (This feature is present only when Serial Port A is set to <i>Enabled</i>)	 3F8 (default) 2F8 3E8 2E8	Sets the base I/O address for serial port A.
Interrupt (This feature is present only when Serial Port A is set to <i>Enabled</i>)	IRQ3 IRQ4 (default)	Sets the interrupt for serial port A.
Serial port B	Disabled	Enables or disables onboard serial port B.
	Enabled (default)	Two devices cannot share the same IRQ. Choosing <i>Disabled</i> makes serial port B unusable.
Base I/O Address (This feature is present only when Serial Port B is set to <i>Enabled</i>)	3F82F8 (default)3E82E8	Sets the base I/O address for serial port B.
Interrupt (This feature is present only when Serial Port B is set to <i>Enabled</i>)	IRQ3 (default) IRQ4	Sets the interrupt for serial port B.
Parallel port	Disabled	Enables or disables the onboard parallel port.
	Enabled (default)	Two devices cannot share the same IRQ. Also, choosing <i>Disabled</i> makes the parallel port unusable.
Mode	Output only	Sets the mode for the parallel port.
(This feature is present	Bi-directional	Output only is the standard printer connection mode.
only when Parallel Port is set to <i>Enabled</i>)	• EPP	Bi-directional is the standard bidirectional mode.
ost to Endology	ECP (default)	EPP is Enhanced Parallel Port mode, a high-speed bidirectional mode. Selection based on what EPP version the printer supports. Only choose a mode that the parallel port device (such as a printer) supports. Check the parallel port device documentation for this information. If this information cannot be located, use the default setting. ECP is Extended Capabilities Port mode, a high-speed bidirectional
		<i>ECP</i> is Extended Capabilities Port mode, a high-speed bidirection mode.

Depending on the **Mode** is selected above, the parallel port configuration options are different:

Output only option selected

Base I/O address	• 378 (default)	Set the base I/O address for parallel port.
	• 278	
	• 3BC	
Interrupt	• IRQ 5	Set the interrupt for parallel port
	 IRQ 7 (default) 	

Bi-directional option selected

Base I/O address	• 378 (default)	Set the base I/O address for the parallel port
	• 278	
	• 3BC	
Interrupt	• IRQ 5	Set the interrupt for parallel port
	• IRQ 7 (default)	

EPP option selected

Interrupt	• IRQ 5	Set the interrupt for parallel port
	 IRQ 7 (default) 	

Note: The "Base I/O address" cannot be changed. Its default value is set to [378]

ECP option selected

Base I/O address	• 378 (default)	Set the base I/O address for parallel port.
	• 278	
	• 3BC	
Interrupt	• IRQ 5	Set the interrupt for parallel port
	• IRQ 7 (default)	
DMA Channel	• DMA 1	Set the DMA Channel for parallel port
	DMA 3 (default)	

Feature	Choices	Description
Floppy disk controller	Disabled	Configure using these options
	Enabled	[Disabled] No Configuration
	(default)	[Enabled] User Configuration

10.1.6.2 On Board Device Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then select On Board Device.

Main	Advanced	Security	Power	Boot	System	Exit	
	I/O Device C	onfiguration					
	On Board D	evice					
	PCI Configur	PCI Configuration					
	Server Menu	Server Menu					
	Console Red	Console Redirection					
	Event Loggin	Event Logging					
	Hardware Mo	onitor					
				1			

Table 53 lists the options available through the On Board Device submenu. This submenu configures the RAID, network, and USB controllers on the board.

Table 53. On Board Device Submenu

Feature	Choices	Description
Onboard Serial	Disabled	Enables the onboard serial ATA.
ATA	Enabled (default)	
Onboard NIC 1	Disabled	Enables the onboard PCI Intel 82550PM Controller.
	Enabled (default)	
Onboard NIC 2	Disabled	Enables the onboard PCI Intel 82540EM Controller.
(Gbit)	Enabled (default)	
Onboard VGA	Single (default)	Determines behavior of on board video:
Behavior	Dual	If [Single] is selected, then the onboard video controller will be disabled when an add-in video card is detected.
		If [Dual] is chosen, then the onboard video controller will be enabled and the primary video controller in a dual video configuration.
Onboard USB	Disabled	Enables the ICH4 USB controller.
1.1	Enabled (default)	
Onboard USB	Disabled (default)	Enables the onboard USB controller.
2.0	Enabled	

10.1.6.3 PCI Configuration Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then PCI Configuration.

Advanced	Security	Power	Boot	System	Exit
O Device Co	onfiguration				
On Board De	vice				
PCI Configur	ation				
Onboard	Serial ATA				
Onboard	NICs				
Slot 1 PCI 32 / 33					
Slot 2 PCI 32 / 33					
Slot 3 PCI-X 64 / 100					
Slot 4 PCI-X 64 / 100					
Slot 5 PCI 64 / 66					
Server Menu					
Console Redirection					
Event Logging					
Hardware Mo	nitor				
	O Device Co On Board Dev Onboard Onboard Slot 1 PO Slot 2 PO Slot 3 PO Slot 5 PO Server Menu Console Redi	O Device Configuration On Board Device PCI Configuration Onboard Serial ATA Onboard NICs Slot 1 PCI 32 / 33 Slot 2 PCI 32 / 33 Slot 3 PCI-X 64 / 100 Slot 4 PCI-X 64 / 100 Slot 5 PCI 64 / 66 Server Menu Console Redirection	O Device Configuration On Board Device OCI Configuration Onboard Serial ATA Onboard NICs Slot 1 PCI 32 / 33 Slot 2 PCI 32 / 33 Slot 3 PCI-X 64 / 100 Slot 4 PCI-X 64 / 100 Slot 5 PCI 64 / 66 Server Menu Console Redirection	O Device Configuration On Board Device OCI Configuration Onboard Serial ATA Onboard NICs Slot 1 PCI 32 / 33 Slot 2 PCI 32 / 33 Slot 3 PCI-X 64 / 100 Slot 4 PCI-X 64 / 100 Slot 5 PCI 64 / 66 Server Menu Console Redirection Event Logging	O Device Configuration On Board Device OCI Configuration Onboard Serial ATA Onboard NICs Slot 1 PCI 32 / 33 Slot 2 PCI 32 / 33 Slot 3 PCI-X 64 / 100 Slot 4 PCI-X 64 / 100 Slot 5 PCI 64 / 66 Server Menu Console Redirection Event Logging

Table 54 lists the options available through the PCI Configuration submenu. This submenu configures the option ROM area for onboard PCI devices.

Table 54. PCI Configuration Submenu

Feature	Choices	Description
Onboard Serial ATA	Select to display submenu	Enables the onboard Serial ATA. See the Option ROM Scan Submenu.
Onboard NICs	Select to display submenu	Configures the onboard NICs. See the Onboard NICs Submenu.
Slot 1 PCI 32 / 33	Select to display submenu	Configures the specific PCI device expansion ROM. See the Option ROM Scan Submenu.
Slot 2 PCI 32 / 33	Select to display submenu	Configures the specific PCI device expansion ROM. See the Option ROM Scan Submenu.
Slot 3 PCI-X 64 / 100	Select to display submenu	Configures the specific PCI device expansion ROM. See the Option ROM Scan Submenu.
Slot 4 PCI-X 64 / 100	Select to display submenu	Configures the specific PCI device expansion ROM. See the Option ROM Scan Submenu.
Slot 5 PCI 64 / 66	Select to display submenu	Configures the specific PCI device expansion ROM. See the Option ROM Scan Submenu.

Table 55 lists the options available in the Onboard Serial ATA submenu. This submenu appears for the Onboard Serial ATA option available in the Advanced PCI Configuration submenu above (see Table 54)

Table 55. Onboard Serial ATA Submenu

Feature	Choices	Description
Option ROM Scan	Enabled (default)	Initializes the device expansion ROM.
	 Disabled 	
Onboard Serial ATA Mode	No options	User information area showing which mode the SATA controller is in: Base ATA or RAID

Table 56 lists the options available in the Onboard NICs submenu. This submenu appears for the Onboard NICs option available in the Advanced PCI Configuration submenu above (see Table 54).

Table 56. Onboard NICs Submenu

Feature	Choices	Description			
Onboard NIC1 PXE	Enabled	Enabled support for onboard Intel 82550PM NIC PXE.			
	Disabled (default)	Note: Once PXE boot is enabled, it will not be selectable in the boot order until after a restart.			
Onboard NIC2 (Gbit) PXE	 Enabled 	Enabled support for onboard Intel 82540EM NIC PXE.			
	Disabled (default)	Note: Once PXE boot is enabled, it will not be selectable in the boot order until after a restart.			

Table 57 lists the options available in the PCI Devices, Slots # 1~5 submenus. This submenu appears for several options available on the Advanced PCI Configuration submenu above (see Table 54). For brevity, only one example is shown.

Table 57. Option ROM Scan Submenu

Feature	Choices	Description
Option ROM Scan	Enabled (default)	Enables/Disables add-in card option ROM expansion by slot.
	 Disabled 	

10.1.6.4 Server Menu Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then select the Server Menu.

Main	Advanced	Security	Power	Boot	System	Exit
	I/O Device C	onfiguration				
	On Board De	vice				
	PCI Configur	ation				
	Server Menu	ı				
	Console Red	lirection				
	Event Loggin	ıg				
	Hardware Mo	onitor				

Table 58 lists the options available through the Server Menu submenu. This submenu allows you to set options for server features.

Table 58. Server Menu Submenu

Feature	Choices	Description
NMI on PERR	Disabled	Enables or disables nonmaskable interrupts (NMI) on parity errors on
	Enabled (default)	the PCI bus (PERRs).
NMI on SERR	Disabled	Enables or disables NMI on system errors on the PCI bus (SERRs).
	Enabled (default)	

10.1.6.5 Console Redirection Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then Console Redirection.

Main	Advanced	Power	Boot	System	Exit
	I/O Device Configuration				
	On Board Device				
	PCI Configuration				
	Server Menu				
	Console Redirection				
	Event Logging				
	Hardware Monitor				

Table 59 lists the options available through the Console Redirection submenu. This submenu provides options to configure console redirection.

Table 59. Console Redirection Submenu

Feature	Choices	Description
COM Port Address	Disabled (default) On-board COM A On-board COM B	When enabled, console redirection uses the I/O port specified. All keyboard/mouse and video will be directed to this port. This setting is designed to be used only under DOS in text mode.
Baud Rate	 300 1200 2400 9600 19.2k (default) 38.4k 57.6K 115.2k 	When console redirection is enabled, specifies the baud rate to be used.
Console Type	VT100 PC ANSI (default)	Enables the specified console type.
Flow Control	None XON/XOFF CTS/RTS (default)	None disallows flow control. XON/XOFF is software-based asynchronous flow control. CTS/RTS is hardware-based flow control. When EMP is sharing the COM port as console redirection, the flow control must be set to CTS/RTS.
Console Connection	Direct (default) Via modem	Indicates whether the console is connected directly to the system or whether a modem is used.
Continue C.R. after POST	• Off (default) • On	Enables console redirection (C.R.) after the operating system has been loaded.

10.1.6.6 Event Logging Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then Event Logging.

Main	Advanced	Security	Power	Boot	System	Exit
	I/O Device C	onfiguration				
	On Board De	vice				
	PCI Configur	ation				
	Server Menu					
	Console Red	irection				
	Event Loggi	ng				
	Hardware Mo	onitor				

Table 60 lists the options available through the Event Logging submenu. This submenu allows you to view the event logs.

Table 60. Event Logging Submenu

Feature	Choices	Description			
Event log validity	No options	Indicates if the contents of the event log are valid.			
Event log capacity	No options	Indicates if there is space available in the event log.			
View event log	<enter></enter>	Select <enter> to display the current event log. Only single bit error (SBE) and multi bit error (MBE) events on the memory bus are supported. No Winbond W83627HF Super I/0 information is available.</enter>			
Event Logging	DisabledEnabled (default)	Enables logging of events.			
ECC Event Logging	DisabledEnabled (default)	Enables logging of ECC events.			
Clear all event logs	• No (default) • Yes	Clears the event log after booting. Automatically resets itself to No after boot. Must be set to Yes if the Event Log Validity option is invalid.			

10.1.6.7 Hardware Monitor Submenu

To access this submenu, select Advanced on the menu bar at the top of the screen and then Hardware Monitor.

Main	Advanced	Security	Power	Boot	System	Exit
	I/O Device Co	onfiguration				
	On Board De	vice				
	PCI Configura	ation				
	Server Menu					
	Console Red	irection				
	Event Loggin	g				
	Hardware Mo	onitor				

Table 61 lists the settings displayed in the Hardware Monitor submenu. This submenu displays temperature, voltages, and fan speeds for the onboard Super I/O Winbond ASIC (the values listed below are for reference only). Use the up and down arrow keys to scroll through the readings.

Table 61. Hardware Monitor Submenu

Feature	Choices	Description
Hardware Monitor IO index / data	No options	Value fluctuates. Example: 0295h/0296h
VCC_CPU_A	No options	Value fluctuates. Example: 1.45 V
+1_8V_A	No options	Value fluctuates. Example: 1.79 V
+3.3_V_A	No options	Value fluctuates. Example: 3.24 V
AVCC	No options	Value fluctuates. Example: 5.02 V
+3V_STBY_A	No options	Value fluctuates. Example: 3.28 V
-12V_CPU_A	No options	Value fluctuates. Example: 11.12 V
+2_5V_A	No options	Value fluctuates. Example: 2.49 V
AUX5V	No options	Value fluctuates. Example: 4.94 V
Ambiance	No options	Value fluctuates. Example: 35 °C /95 °F
CPU1	No options	Value fluctuates. Example: 51 °C/123 °F
CPU2	No options	Value fluctuates. Example: 34 °C/93 °F
CPU FAN 1 speed	No options	Value fluctuates. Example: 4560 RPM
CPU FAN 2 speed	No options	Value fluctuates. Example: 4560 RPM
Sys FAN 1 speed	No options	Value fluctuates. Example: 5260 RPM
Sys FAN 2 speed	No options	Value fluctuates. Example: 4560 RPM
Sys FAN 3 speed	No options	Value fluctuates. Example: 4560 RPM
Sys FAN 4 speed	No options	Value fluctuates. Example: 4560 RPM

10.1.7 Security Menu

To access this menu, select Security on the menu bar at the top of the screen.

Main	Advanced	Security	Power	Boot	System	Exit
		_				

Table 62 lists the options available on the Security menu. Enabling the Supervisor Password field requires a password for entering Setup. The passwords are not case-sensitive.

Table 62. Security Menu

If no password ent	f no password entered previously:				
Feature	Choices	Description			
Set Supervisor Password	<enter></enter>	The supervisor password controls access to the BIOS Setup utility. When the <enter> key is pressed, you are prompted for a password; press the ESC key to abort.</enter>			
		This password can be set only if a supervisor password is entered.			
		When the user has entered his or her name but the supervisor is not logged in, only the following information is accessible:			
		Supervisor password is set to Enabled.			
		User password is set to Enabled.			
		Set user password [press enter] to enter a user password.			
		Password on boot is set to <i>Enabled/Disabled</i> (whichever is in effect). This option is not allowed to change.			
Set User <enter> Password</enter>		The user password controls access to the system at boot. When the <enter> key is pressed, you are prompted for a password; press the ESC key to abort.</enter>			
		The supervisor password must be set if a user password is to be used.			
		NOTE: Entering Setup with a supervisor password provides full access to all BIOS Setup utility menus.			
Password on boot	Disabled (default) Enabled	Requires password entry before boot. System will remain in secure mode until password is entered. If a user or supervisor password is not entered, the operating system cannot be accessed.			
Diskette access	User (default)	Controls who can access diskette drives.			
		Supervisor limits access to the diskette drive to the supervisor, who must enter a password.			
		User allows access to the diskette drive by entering either the supervisor or the user password.			
		Whatever setting is chosen, it becomes functional only if both a supervisor password and a user password have been set (if the User setting is chosen).			

10.1.8 Power Menu

To access this menu, select Power on the menu bar at the top of the screen

Main	Advanced	Security	Power	Boot	System	Exit

Table 63 lists the options available on the Power menu. This menu is designed to configure various aspects of the powering on or off of the board.

Table 63. Power Menu

Feature	Choices	Description
Power Loss Control	Stay Off	Specifies the power level the system returns to after AC power is lost.
	Last State (default)	Stay Off leaves the server power disabled and ACPI does not function to reboot the server in the event of a power failure.
		Last State reboots the system according to ACPI standards.
Power Button	Disabled	Enables or disables the power button functionality.
	• Enabled (default)	

10.1.9 Boot Menu

To access this menu, select Boot on the menu bar at the top of the screen

Main	Advanced	Security	Boot	System	Exit	
		•		,		

Table 64 lists the options available on the Boot menu. This menu allows you to set the boot priority of devices installed in the system. Use the following key combinations to navigate between or view the devices and change the boot priority:

- <Enter> expands or collapses devices with a "+" or "-."
- <Ctrl+Enter> expands all devices.
- <Shift+1> enables or disables devices.
- <+> and <-> moves the device up or down.
- <n> may move the removable device between the hard drive or removable disk.
- <d> removes a device that is not installed.

Table 64. Boot Menu

Boot Priority	Device	Description	
1 st Boot Device 2 nd Boot Device 3 rd Boot Device	Removable DevicesHard Drive	Specifies the boot sequence according to the device type. The computer will attempt to boot from up to four devices as specified here. Only one of the devices can be an IDE hard disk drive. The default settings for the first through fourth boot devices are, respectively:	
4 th Boot Device	CD-ROM Drive		
	 Network Boot 	Removable Devices: Attempts to boot from the diskette drive or a removable device, such as the floppy.	
		Hard Drive: Attempts to boot from a hard drive device.	
		CD-ROM Drive: Attempts to boot from a CD-ROM drive containing bootable media. This entry appears if there is a bootable CD-ROM that is in a BIOS Boot Specification (BBS)—compliant SCSI CD-ROM.	
		 Network Boot: If the network card ROM contains the string \$PnP, it uses the correct BBS and the device will appear the Boot menu as an independent device. 	

10.1.10 System Menu

To access this menu, select System on the menu bar at the top of the screen

Main Advanced Securi	ity Power Boot	System Exit
----------------------	----------------	-------------

Table 65 lists the options available on the System menu. This menu displays information on vendor, processor, memory, peripherals, and BIOS.

Table 65. System Menu

Feature	Choices	Description	
Machine Vendor	<enter></enter>	Provides basic information on the machine vendor:	
		Manufacturer: Intel Corporation	
		Product: SE7505VB2	
		Version: 1.00	
		Serial Number: [varies]	
CPU	<enter></enter>	Provides basic information on the processor	
		Boot Strap Processor:	
		Installed Speed: 2.8 GHz (for example)	
		Socket Name: BSP	
		Manufacturer: GenuineIntel	
		Version: Intel(R) XEON(TM)	
		CPUID: 3FEBFBFF00000F24	
		• L2 Cache: 512 KB	
		Application Processor:	
		Installed Speed: 2.8 GHZ (for example)	
		Socket Name: AP	
		Manufacturer: GenuineIntel	
		Version: Intel(R) XEON(TM)	
		CPUID: 3FEBFBFF00000F24	
		L2 Cache: 512 KB	
Memory	<enter></enter>	Provides basic information on the memory:	
		System Memory: 640 KB	
		Extended Memory: 1023 MB (BIOS based memory)	
		Shadow RAM: 384 KB	
		Cache RAM: 512 KB	
		Installed Size—DIMM 1A, 1B, 2A, and 2B: DIMM size in MB	

Feature	Choices	Description			
Peripherals	<enter></enter>	Provides the port connectors for onboard designators. None of these can be modified in user mode			
		Port Connector	On Board Designator	Port Connector	On Board Designator
		J8A1 & J2J4	Serial A & Serial B	J3K2	Floppy
		J7A2	Parallel	J7A1	Video
		J9A1	KB/MS	J5A1	NIC2 (Gbit)
		J3K3	Primary IDE	J6A1	NIC1
		J4K1	Secondary IDE		
		J1H2 & J1H1	SATA1 & SATA2	J9A2 & J5K1	USB
BIOS	<enter></enter>	ROM SIZE: 1024 KB			
		Vendor: Pho	enix Technologies	LTD	
		Version: 1.01	1		
		Release Date	e: 01/15/2003		

10.1.11 Exit Menu

To access this menu, select Exit on the menu bar at the top of the screen

Main Advanced	Security	Power	Boot	System	Exit	
---------------	----------	-------	------	--------	------	--

Table 66 lists the options available in the Exit menu. Select an option using the up or down arrow keys; then press <Enter> to execute the option. Pressing <Esc> does not exit this menu. You must select one of the items from the menu or menu bar to exit.

Table 66. Exit Menu

Choices	Description	
Exit Saving Changes	Exits after writing all modified Setup item values to CMOS.	
Exit Discarding Changes	Exits leaving CMOS unmodified. User is prompted if any of the setup fields were modified.	
Load Setup Defaults	Loads default values for all Setup items.	
Discard Changes	Reads previous values of all Setup items from CMOS.	
Save Changes	Writes all Setup item values to CMOS.	
Load Custom Default	Loads custom default values for all setup items.	
Save Custom Default	Saves all Setup item values to NVRAM as a custom default.	

10.2 Upgrading the BIOS

10.2.1 Preparing for the Upgrade

Before you upgrade the BIOS, prepare for the upgrade by recording the current BIOS settings, obtaining the upgrade utility, reviewing the release notes, and making a copy of the current BIOS.

10.2.1.1 Recording the Current BIOS Settings

1. Boot the computer and press <F2> when you see the message:

```
Press <F2> Key if you want to run SETUP
```

2. Write down the current settings in the BIOS Setup program or go to the Exit menu and choose to "Save Custom Defaults".

Note: Do not skip step 2. You will need these settings to configure your computer at the end of the procedure.

If you chose to "Save Custom Defaults," after the new BIOS is flashed, you can restore your settings from the "Load Custom Default" option.

10.2.1.2 Obtaining the Upgrade Utility

You can upgrade to a new version of the BIOS using the new BIOS files and the BIOS upgrade utility, *PHLASH16.EXE*. You can obtain the BIOS upgrade file and the PHLASH.EXE utility from the Intel Customer Support Web site:

http://support.intel.com/support/motherboards/server/SE7505VB2

Note: Please review the instructions distributed with the upgrade utility before attempting a BIOS upgrade. Review also any release notes that accompany the new version of the BIOS. The release notes may contain critical information regarding jumper settings, specific fixes, or other information to complete the upgrade.

Note: The *PHLASH16.EXE* program will not work in a HIMEM controlled DOS environment by default. You'll need to add the '/X' switch after the *PHLASH16.EXE* command to enable your BIOS Update to work if HIMEM is loaded.

This upgrade utility allows you to upgrade the BIOS in flash memory. The following steps explain how to upgrade the BIOS.

10.2.1.3 Creating a Bootable Diskette

- 1. Use a DOS system to create the diskette.
- 2. Insert a diskette in diskette drive A.
- 3. At the C:\ prompt, for an unformatted diskette, type:

```
format a:/s
```

or, for a diskette that has already been formatted, type:

```
sys a:
```

4. Press <Enter>.

10.2.1.4 Creating the BIOS Upgrade Diskette

The BIOS upgrade file is a compressed self-extracting archive that contains the files you need to upgrade the BIOS.

- 1. Download the BIOS image file to a temporary folder on your hard drive. The image is available from http://support.intel.com/support/motherboards/server/SE7505VB2
- 2. Execute the BIOS.EXE file to extract the update files from the image file.
- 3. Insert the bootable diskette you created in the steps above into the diskette drive.
- 4. Copy the BIOS update files from the temporary folder onto the bootable diskette.

10.2.2 Upgrading the BIOS

Note: Make sure to read your BIOS release notes for any specific instructions on updating the BIOS (i.e. special jumper settings).

- 1. Place the bootable diskette containing the BIOS update files into the diskette drive of your system. Boot the system with the diskette in the drive.
- 2. A menu will appear with two options. Use option 1 to automatically update the system BIOS (See step 3).
 - Use option 2 to manually update the system BIOS and the User Binary (See step 4).
- 3. If you selected option 1, to automatically update the system BIOS: The system will execute the Phlash update utility and update the BIOS. When the update is complete, the utility will display a green box with a message that says "Completed Successfully." The system will then reboot. Skip to step 5.

- 4. If you selected option 2, to manually update the BIOS or to update the flash memory, you can either select "Update Flash Memory From a File" or "Update System BIOS":
 - Update Flash Memory From a File: When prompted for a file name, type BIOS.wph and press Enter.
 - Update System BIOS: The system will warn you that the BIOS will be updated.
 Verify the BIOS version is correct and press Enter to continue. When the update is complete, the utility will display a green box with a message that says "Completed Successfully." The system will then reboot.
- 5. Wait while the BIOS files are updated. Do **not** power down the system during the BIOS update process! The system should reset automatically when the BIOS update process is completed. If it does not and the green box is displayed, go ahead and reboot the machine manually. Remove the diskette from the diskette drive.
- 6. Check to make sure the BIOS version displayed during POST is the new version as the system reboots.
- 7. Enter Setup by pressing the F2 key during boot. Once in Setup, press the F9 and <Enter> to set the parameters back to default values. If you do not set the CMOS values back to defaults using the F9 key, the system may function erratically.
- 8. Re-enter the values you wrote down at the beginning of this process, or if you saved your Custom Defaults, reload them by choosing from the Exit menu, the Load Custom Defaults option. Press F10 and <Enter> to exit BIOS Setup and Save Changes.

Note: You may encounter a CMOS Checksum error or other problem after reboot. Try shutting down the system and booting up again. CMOS checksum errors require that you enter Setup, check your settings, save your settings, and exit Setup.

10.2.3 Crisis Recovery Diskette

It is unlikely that anything will damage the BIOS; however, a recovery disk should be created to ensure a quick recovery should it happen. The following steps explain how to create the crisis recovery diskette.

You can obtain the Crisdisk.exe file needed to create the crisis disk from the Intel Customer Support Web site: http://support.intel.com/support/motherboards/server/SE7505VB2

10.2.3.1 Creating the Crisis Recovery Diskette

Note: The crisis recovery diskette must be created on a Windows 98, Windows 2000, or Windows XP system.

Use the following steps to create the diskette:

- 1. Create an empty folder at the Windows workstation.
- 2. Copy the Crisdisk.exe folder into the folder and execute the command Crisdisk to extract the contents of the self-extracting file into the folder.
- 3. Insert an empty diskette into the A: drive.
- 4. While in the folder with the Crisdisk contents, type Wincris.
- 5. You will be prompted by a screen that contains three options:
 - Create MINIDOS Crisis Disk: Installs the necessary recovery files onto the A: drive.
 Use this option if the diskette you are using is already formatted and bootable.
 - Create FULLDOS Crisis Disk: Makes the floppy disk in A: bootable and then installs the necessary recovery files. Use this option if the diskette you are using is blank, but not bootable.
 - Format the A: Drive Diskette: Formats the diskette in the A: drive. Use this option if the diskette is not blank. When this option is complete, you will then need to use the "Create FULLDOS Crisis Disk option."

When the crisis diskette has been created, you will be prompted with a message to remove the diskette. You will then be asked whether you want to create additional crisis diskettes.

10.2.3.2 Manually Recovering the BIOS

A BIOS recovery can also be manually initiated. This option would be used only when the BIOS is corrupt, but the ROM checksum error does not occur during POST. To manually initiate a BIOS recovery, use the following steps:

- 1. Power down and unplug the system from the AC power source.
- 2. Move the recovery jumper at J4J1 from the storage position at pins 9 and 10 to cover pins 3 and 4. See the figure below.

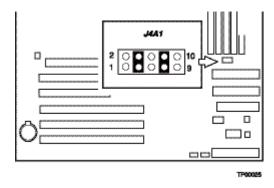


Figure 11. BIOS Recovery Jumper

- 3. Insert the Crisis Recovery Diskette into the A: diskette drive.
- 4. Plug the system into the AC power source and power it on.
- 5. A blue screen will be displayed and the recovery process will automatically run. The system will continue to beep throughout the recovery process. The recovery process is complete when the beeping stops.
- 6. Remove the diskette.
- 7. Power down and unplug the system from the AC power source.
- 8. Move the BIOS recovery jumper at J4J1 back to the original position, covering storage pins 9 and 10.
- 9. Plug the system into the AC power source and power it up to confirm that the recovery was successful.

10.3 Error Handling and Reporting

10.3.1 POST Error Beep Codes

Table 67. POST Error Beep Codes

Beeps	Reason
4-3-1-2	No memory DIMM(s)
4-3-1-3	Memory type is mismatch
4-3-1-4	No DIMM Pair(s) in System
4-3-3-1	Memory Error Row Address Bits
4-3-3-2	Memory Error Internal Banks
4-3-3-3	Memory Error Timing
4-3-3-4	Memory Error Register CAS 3
4-3-4-1	Memory Error Register NonReg Mix
4-3-4-2	Memory Error CAS Latency
4-3-4-3	Memory Error Size Not Supported
1-3-4-3	Memory Failure prior to 4MB

10.3.2 BIOS Event Log

The SE7505VB2 contains a small amount of space in the BIOS to record errors or failures during post. Below is a table of these events and their meaning:

Table 68. BIOS Event Log Error Messages

The event	The Event Log Message	Post Code
Timer failed	Channel 2 Timer Not Functional	A0h
CMOS Battery Failure	CMOS Battery Failure	09h
CMOS Checksum Error	CMOS Checksum Error	09h
Floppy failure	Floppy Drive A Error	8Ch
Keybord stuck key	Keyboard not functional – stuck key	52h
Keyboard not functional	Keyboard not functional	70h
The keyboard controller failed	Keyboard Controller not functional	70h
The memory size decreased	Memory size decreased	C2h
Invalide date and time of RTC	CMOS Time not set	09h
Different speed of CPUs	Different speed of CPUs installed	70h
Different type of CPUs	Different type of CPUs installed	70h
CPU BIST failed	CPU BIST failure	93h
Invalid NIC 1 (100Mb)	Invalid NIC1 (100Mb) SSID/SSVID	70h
Single bit error	Correctable memory errors	After 62h (uses SMI to log event)
Multiple bit error	Un-correctable memory errors	After 62h

11. Absolute Maximum Ratings

Operating the board at conditions beyond those shown in the following table may cause permanent damage to the system. The table is provided for stress testing purposes only. Exposure to absolute maximum rating conditions for extended periods may affect system reliability.

Table 69. Absolute Maximum Ratings

Operating Temperature	5 °C to 50 °C ¹
Storage Temperature	-55 °C to +150 °C
Voltage on any signal with respect to ground	-0.3 V to Vdd + 0.3V ²
3.3 V Supply Voltage with Respect to ground	-0.3 V to 3.63 V
5 V Supply Voltage with Respect to ground	-0.3 V to 5.5 V

Notes:

- 1. Chassis design must provide proper airflow to avoid exceeding the processor maximum case temperature.
- 2. VDD means supply voltage for the device

11.1 Mean Time Between Failures (MTBF) Test Results

This section provides results of MTBF testing done by a 3rd party testing facility. MTBF is a standard measure for the reliability and performance of the board under extreme working conditions. For the SE7505VB2 server board, MTBF was measured at 108,000 hours at 55 degrees Centigrade.

12. Power Information

12.1 SE7505VB2 Server Board Power Budget

The following table shows the power consumed on each supply line for the SE7505VB2 baseboard that is configured with two processors (each 68W max) and Intel Xeon processors w/512k cache FMB TDP. This configuration includes four 2GB DDR DIMMs stacked burst at 70% max. The numbers provided in the table should be used for reference purposes only. Different hardware configurations will produce different numbers. The numbers in the table reflect a common usage model operating at a higher than average stress levels.

Table 70. The Board Power Budget

Items	Q'ty	Max Power		Average power	Out	lax Cu		Output Average Current (V)				V)				
System Board					+5	+3.3	+12	-12	-5	+5 VSB	+5	+3.3	+12	-12	-5	+5 VSB
Processor Vcore	2	177.22		160.00			18.46						16.67			
Processor VRD Eff@ 80%		35.44	20%	32.00												
NB (Intel E7505 MCH)																
1.5V / 0.6A	1	0.90	80%	0.72		1.04						0.833				
E7505 Vcore (1.475V / 2.1A)	1	3.10	65%	2.01		1.41						0.92				
2.5V/6.8 A	1	17.00	65%	11.05	3.63						2.36					
1.475 V VRD Eff @80%		0.18	20%	0.14												
1.2 V VRD Eff @80%		0.62	20%	0.40												
2.5 V VRD Eff @80%		3.40	20%	2.21												
SB (ICH4)																
Vcc 3.3 V		2.01	65%	1.31		0.61						0.397				
Vcc 1.5 V		1.46	65%	0.95		0.97						0.631				
Memory DDR 2662	4															
DDR 2.5V (FAN 5057)		51.88	70%	36.31	12.969						9.08					
Vtt 1.25V (FAN 5066)		7.75	70%	5.43		2.94						2.055				
2.5 V VRD Eff @80%		10.38	20%	7.26												
1.25 V VRD Eff @80%		1.55	20%	1.09												
P64H2																
Vcc 3.3V	2	17.16	70%	12.01		2.60						1.820				
Vcc1.8V (SC 1548)	2	19.15	70%	13.41		5.32						3.724				
1.8 V VRD Eff @80%		3.83	20%	2.68												
82540 GIGABIT																
3.3V	1	0.48	70%	0.33		0.15						0.102				
2.5V	1	0.00	70%	0.00	0.12						0.09					
1.5V	1	0.32	70%	0.22		0.21						0.150				
VGA RAGE II XL	1	1.15	80%	0.92	0.23	0.39					0.18	0.312				

BMC AUX5V	1	0.42	65%	0.27				0.08				0.054
AUX3.3V	1	0.30	65%	0.20				0.09				0.059
Super I/O (W83627HF)	1	0.75	80%	0.60		0.23		0.15		0.181		0.121
NIC 82559 Network chip	2	1.95	80%	1.25				0.39				0.250
CLK3.3 (CY28329 Generator)	1	1.35	80%	1.08		0.27				0.216		
Video RAM (2MX 32)	1	0.99	80%	0.79		0.30				0.240		
System ROM (FWH)	1	0.04	80%	0.03		0.01				0.010		
Others		7.50	50%	3.75	1.50				0.75			
USB	2	5.00	50%	2.50	1.00				0.50			
Keyboard	1	0.75	50%	0.38	0.15				0.08			
Mouse	1	0.63	50%	0.31	0.13				0.06			
System Fan	4	9.90	75%	7.43			1.98				1.49	
CPU Fan	2	4.80	75%	3.60			0.48				0.36	
Board Level output current									13.09	11.585	18.51	0.484

12.2 Power Supply Specifications

This section provides power supply design guidelines for the baseboard, including voltage and current specifications, and power supply on/off sequencing characteristics.

Power Supply voltage specification is based on the SSI EPS12V (Entry Power Supply) specification, Revision 1.6.

Parameter	Min	Nom	Max	Units	Tolerance
+3.3 V	3.20 V	+3.30	3.46 V	V_{rms}	+5 / -3 %
+5 V	4.80 V	+5.00	5.25 V	V _{rms}	+5 / -4 %
+12 V	11.52 V	+12.00	12.6 V	V _{rms}	+5 / -4 %
-12 V	-11.40	-12.20	-13.08	V _{rms}	+9 / -5 %
+5 VSB	4.80 V	+5.00	5.25 V	V _{rms}	+5 / -4 %

Table 71. The Board Power Supply Voltage Specification

12.2.1 Power Timing

This section discusses the timing requirements for operation with a single power supply. The output voltages must rise from 10% to within regulation limits (T_{vout_rise}) within 5 ms to 70 ms. The +3.3 V, +5 V and +12 V output voltages start to rise approximately at the same time. All outputs must rise monotonically. The +5 V output must be greater than the +3.3 V output during any point of the voltage rise, however, never by more than 2.25 V. Each output voltage shall reach regulation within 50 ms (T_{vout_on}) of each other and begin to turn off within 400 ms (T_{vout_off}) of each other. The following figure shows the output voltage timing parameters.

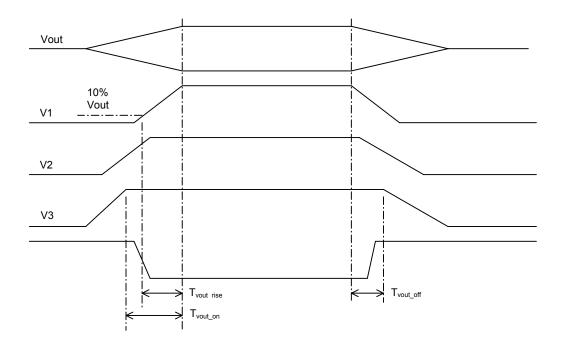


Figure 12. Output Voltage Timing

The following tables show the timing requirements for a single power supply being turned on and off via the AC input, with PSON held low and the PSON signal, with the AC input applied. The ACOK# signal is not being used to enable the turn on timing of the power supply.

Table 72. Voltage Timing Parameters

Item	Description	Min	Max	Units
T _{vout_rise}	Output voltage rise time from each main output.	5	70	msec
T _{vout_on}	All main outputs must be within regulation of each other within this time.		50	msec
T _{vout_off}	All main outputs must leave regulation within this time.		400	msec

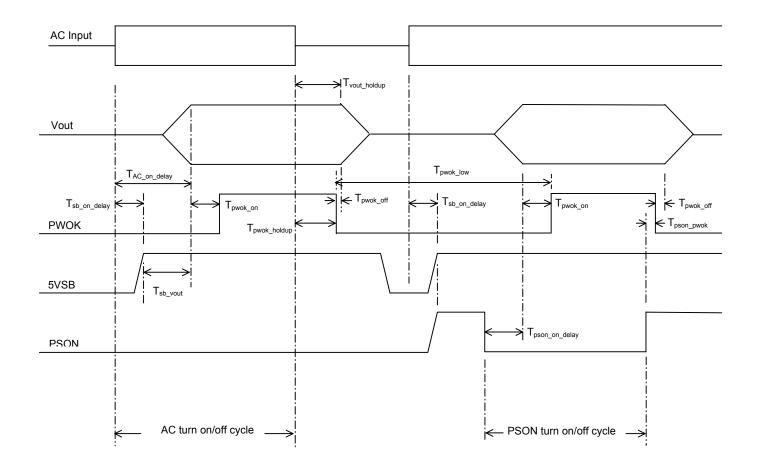


Figure 13. Turn on / off Timing

Table 73. Turn On / Off Timing

Item	Description	Min	Max	Units
T _{sb_on_delay}	Delay from AC being applied to 5VSB being within regulation.		1500	msec
T ac_on_delay	Delay from AC being applied to all output voltages being within regulation.		2500	msec
T _{vout_holdup}	Time all output voltages stay within regulation after loss of AC.	18		msec
T _{pwok_holdup}	Delay from loss of AC to de-assertion of PWOK	17		msec
T _{pson_on_delay}	Delay from PSON [#] active to output voltages within regulation limits.	5	400	msec
T _{pson_pwok}	Delay from PSON [#] deactive to PWOK being de-asserted.		50	msec
T _{pwok_on}	Delay from output voltages within regulation limits to PWOK asserted at turn on.	200	1000	msec
T pwok_off	Delay from PWOK de-asserted to output voltages (3.3V, 5V, 12V, -12V) dropping out of regulation limits.	1		msec
T_{pwok_low}	Duration of PWOK being in the de-asserted state during an off/on cycle using AC or the PSON signal.	100		msec
T _{sb_vout}	Delay from 5 V SB being in regulation to O/Ps being in regulation at AC turn on.	50	1000	msec

Output

+3.3 V

+5 V

+12 V

-12 V

+5 VSB

Step Load

Size 4.8 A

3.0 A

10.4 A

500 mA

325 mA

0.50 A/μs

0.50 A/μs

0.50 A/μs

12.2.2 Voltage Recovery Timing Specifications

Min. Load

Min. Load

Min. Load

The power supply must conform to the following specifications for voltage recovery timing under load changes:

- Voltage shall remain within +/- 5% of the nominal set voltage on the +5 V, +12 V, 3.3 V, -5 V and -12 V output, during instantaneous changes in load shown in the following table.
- Voltage regulation limits shall be maintained over the entire AC input range and any steady state temperature and operating conditions specified.
- Voltages shall be stable as determined by bode plot and transient response. The combined error of peak overshoot, set point, regulation, and undershoot voltage shall be less than or equal to +/-5% of the output voltage setting. The transient response measurements shall be made with a load changing repetition rate of 50 Hz to 5 kHz. The load slew rate shall not be greater than 0.2 A /μs.

Starting LevelFinishing LevelSlew Rate30Min. LoadMin. load + 4.8 A and step up to max. load0.50 A/μs30Min. LoadMin. load + 3.0 A and step up to max. load0.50 A/μs

Min. load + 10.4 A and step up to max. load

Min. load + 500 mA and step up to max. load

Min load +325 mA and step up to max. load

Table 74. Transient Load Requirements

13. Product Regulatory Compliance

13.1.1 Product Safety Compliance

The Intel Server Board SE7505VB2 complies with the following safety requirements:

- UL60 1950 CSA60 950 (USA/Canada)
- EN 60 950 (CENELEC Europe)
- IEC60 950 (International)
- CE Low Voltage Directive 73/23/EEE (CENELEC Europe)
- CB Certificate & Report, IEC60 950
- GOST R (Russia)

13.1.2 Product EMC Compliance

The board system has been tested and verified to comply with the following electromagnetic compatibility (EMC) regulations when installed in a compatible Intel host system. For information on compatible host system(s), contact your local Intel representative.

- FCC /ICES-003, Class A Emissions (USA/Canada) Verification
- CISPR 22Class A Emissions (International)
- EN55022, Class A Emissions (CENELEC Europe)
- EN55024: 1998, Immunity (CENELEC Europe)
- CE EMC Directive 89/336/EEC (CENELEC Europe)
- VCCI, Class A Emissions (Japan)
- AS/NZS 3548 Class A Emissions (Australia / New Zealand)
- BSMI CNS13438 Class A Emissions (Taiwan)
- GOST R 29216-91, Class A Emissions (Russia)
- GOST R 50628-95, Immunity
- RRL, MIC Notice No. 1997-41 (EMC) & 1997-42 (EMI) (Korea)

13.1.3 Mandatory / Standard: Certifications; Registration; Declarations

- cURus Certification (US/Canada) Server Baseboards Only (UL Recognition)
- CE Declaration of Conformity (CENELEC Europe)
- C-Tick Declaration of Conformity (Australia)
- MED Declaration of Conformity (New Zealand)
- BSMI Certification (Taiwan)
- GOST R Certification (Russia)
- RRL Certification (Korea)

13.1.4 Other Product Mandatory Regulations to Consider due to new Emerging International Requirements

Note: The use of telecommunication devices such as modems and/or wireless devices, have not been planned for with respect to these systems and/or board products. If there is any change of plan to use such devices, then telecommunication type certifications will require additional planning. If NEBS compliance is required for system level products, additional certification planning and design will be required.

13.1.5 Important Product Regulation Requirements

- All plastics used must be made of a UL recognized material, and have the appropriate flame ratings mandated by IEC60 950
- All plastics parts shall be manufactured by an UL approved fabricator and the parts shall be marked with the appropriate UL traceability markings.
- All plastic parts shall have not use brominated flame retardants or any other halogenated retardants that are not accepted by environmental programs such as Blue Angels, Nordic White Swan, Swedish TCO.
- All plastic parts shall be marked with the ISO11469 requirements for recycling.
- All wiring harnesses shall be sourced from a UL approved wiring harness manufacturer.
- All Fans shall have the minimum certifications: UL and TUV or VDE
- All external power connectors shall have current limiting devices that have UL and TUV
 or VDE certifications and shall be suitable rated for the application where the device in
 its application complies with IEC60 950.
- All lithium batteries shall be UL recognized and have suitable reverse bias current protection for the application it is used in.
- All printed wiring boards shall be rated UL94V-0 and be sourced from a UL approved printed wiring board manufacturer
- All connectors shall be UL recognized and have a UL flame rating of UL94V-0
- Product safety label must be printed on UL approved label stock and printer ribbon.
 Alternatively labels can be purchased from a UL approved label manufacturer.

13.1.6 Product Regulatory Compliance Markings

This product is provided with the following Product Certification Markings.

- cURus Recognition Mark
- CE Mark
- Russian GOST Mark
- Australian C-Tick Mark
- Korean RRL MIC Mark
- Taiwan BSMI DOC Marking & BSMI EMC Warning
- ICES-003 Marking

13.2 Electromagnetic Compatibility Notices

13.2.1 Europe (CE Declaration of Conformity)

This product has been tested in accordance too, and complies with the Low Voltage Directive (73/23/EEC) and EMC Directive (89/336/EEC). The product has been marked with the CE Mark to illustrate its compliance.

13.2.2 Australian Communications Authority (ACA) (C-Tick Declaration of Conformity)

This product has been tested to AS/NZS 3548, and complies with ACA emission requirements. The product has been marked with the C-Tick Mark to illustrate its compliance.

13.2.3 Ministry of Economic Development (New Zealand) Declaration of Conformity

This product has been tested to AS/NZS 3548, and complies with New Zealand's Ministry of Economic Development emission requirements.

13.2.4 BSMI (Taiwan)

The BSMI DOC Mark is silk screened on the component side of the server board; and the following BSMI EMC warning is located on solder side of the server board.

警告使用者:

這是甲類的資訊產品,在居住的環境中使用時,可能會造成射頻干擾,在這種情況下,使用者會被要求採取某些適當的對策。

13.3 Replacing the Back up Battery

The lithium battery on the server board powers the real time clock (RTC) for up to 10 years in the absence of power. When the battery starts to weaken, it loses voltage, and the server settings stored in CMOS RAM in the RTC (for example, the date and time) may be wrong. Contact your customer service representative or dealer for a list of approved devices. The recommended replacement battery is the Toshiba CR-2032 3V.



WARNING

Danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type recommended by the equipment manufacturer. Discard used batteries according to manufacturer's instructions.



ADVARSEL!

Lithiumbatteri - Eksplosionsfare ved fejlagtig håndtering. Udskiftning må kun ske med batteri af samme fabrikat og type. Levér det brugte batteri tilbage til leverandøren.



ADVARSEL

Lithiumbatteri - Eksplosjonsfare. Ved utskifting benyttes kun batteri som anbefalt av apparatfabrikanten. Brukt batteri returneres apparatleverandøren.



A VARNING

Explosionsfara vid felaktigt batteribyte. Använd samma batterityp eller en ekvivalent typ som rekommenderas av apparattillverkaren. Kassera använt batteri enligt fabrikantens instruktion.



A VAROITUS

Paristo voi räjähtää, jos se on virheellisesti asennettu. Vaihda paristo ainoastaan laitevalmistajan suosittelemaan tyyppiin. Hävitä käytetty paristo valmistajan ohjeiden mukaisesti.

14. Mechanical Specifications

The following figure shows the server board mechanical drawing.

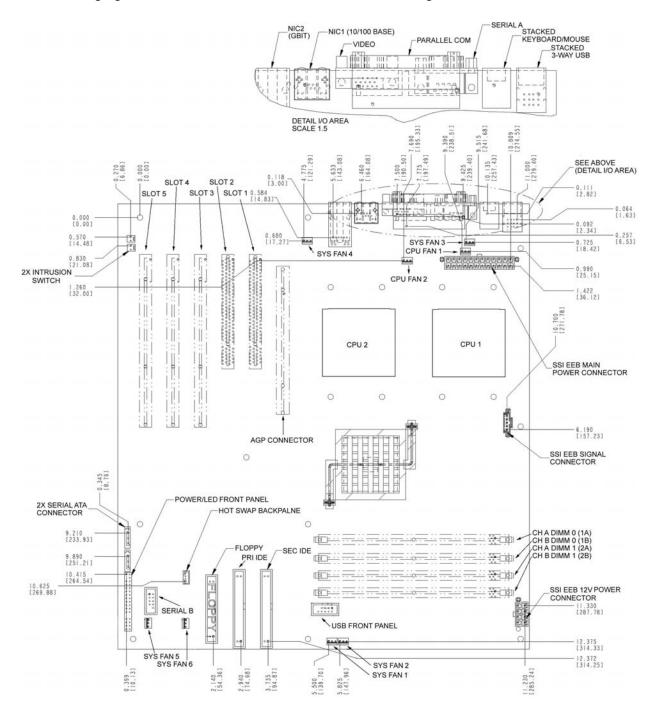


Figure 14. Intel Server Board SE7505VB2 Mechanical Drawing

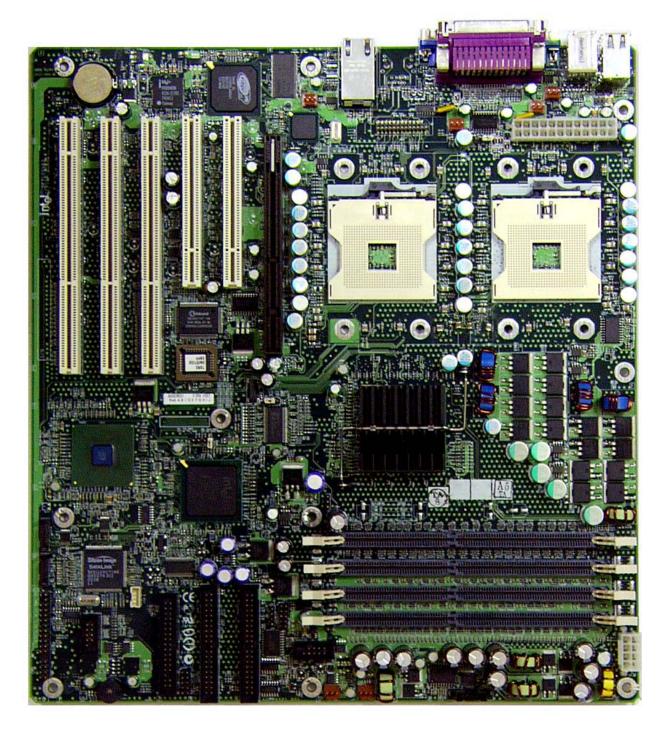


Figure 15. Board Photograph (Reference Only)

Glossary

This appendix contains important terms used in the preceding chapters. For ease of use, numeric entries are listed first (e.g., "82460GX") with alpha entries following (e.g., "AGP 8x"). Acronyms are then entered in their respective place, with non-acronyms following.

Term	Definition
ACPI	Advanced Configuration and Power Interface
ASIC	application specific integrated circuit
BIOS	Basic input/output system
BIST	Built-in self test
Bridge	Circuitry connecting one computer bus to another, allowing an agent on one to access the other.
BSP	Bootstrap processor
Byte	8-bit quantity.
CMOS	In terms of this specification, this describes the PC-AT compatible region of battery-backed 128 bytes of memory, which normally resides on the server board.
ICH4	I/O Controller Hub 4
ECC	Error Checking and Correction
ECP	Extended Capabilities Port
EMP	Emergency management port.
EPP	Enhanced Parallel Port mode
EPS	External Product Specification
FRU	Field replaceable unit
GB	1024 MB.
GPIO	General purpose I/O
Hz	Hertz (1 cycle/second)
I2C	Inter-integrated circuit bus
IA	Intel® architecture
IERR	Internal error
IP	Internet Protocol
IPMB	Intelligent Platform Management Bus
ITP	In-target probe
KB	1024 bytes.
LAN	Local area network
LPC	Low pin count
MB	1024 KB
MCH	Intel® E7505 chipset Memory Controller Hub
Ms	milliseconds
Mux	multiplexor
NIC	Network Interface Card
NMI	Non-maskable Interrupt
OEM	Original equipment manufacturer
Ohm	Unit of electrical resistance
P32-A	32-bit PCI Segment
P64-B	Full Length 64/100 MHz PCI Segment
P64-C	low-profile 64/133 MHz PCI Segment

P64H2	Intel® PCI-X 64-bit Hub 2
PBGA	Pin Ball Grid Array
POST	Power-on Self Test
RAM	Random Access Memory
RISC	Reduced instruction set computing
ROM	Read Only Memory
SDRAM	Synchronous Dynamic RAM
SMI	Server management interrupt. SMI is the highest priority nonmaskable interrupt.
TBD	To Be Determined
UART	Universal asynchronous receiver and transmitter
USB	Universal Serial Bus
Word	16-bit quantity

Reference Documents

Refer to the following documents for additional information:

- PCI Local Bus Specification Revision 2.3
- PCIX 1.0
- PCI Bus Power Management Interface Specification 1.1
- ATI Rage XL Graphics Controller Specifications, Technical Reference Manual, Rev 2.01
- VRM 9.1 Specification
- I2C Bus Specification
- USB 2.0
- Intel[®] Server Board SE7505VB2 BIOS EPS²
- SSI-EEB 3.0
- Windows Logo/SDG 3.0
- ACPI 1.0b
- SMBIOS 2.3.1
- PC2001 (only if WS cert)
- AGP 3.0 Spec
- AGP Design Guide Rev 1.5
- AGP Pro 1.1 Spec Rev 1.1a

² This document is not available as a downloadble file, please contact your Intel field representative to obtain this document